TPS785-Q1
具有高精度和使能功能的 1A、高 PSRR 低压差稳压器

1 特性

- 符合面向汽车应用的 AEC-Q100 标准：
  - 温度等级 1：–40°C 至 +125°C，T_A
- 器件结温：–40°C 至 +150°C，T_J
- 输入电压范围：1.7V 至 6.0V
- 可提供以下输出电压：
  - 可调节选项：1.2V 至 5.5V
  - 固定选项：0.65V 至 5.0V
- 输出精度：典型值为 0.5%，最大值为 1.7%
- 低 I_Q：25 μA（典型值）
- 超低压降：
  - 1A 电流时为 315mV（最大值）($3.3V_{OUT}$)
- 内部软启动时间为 550 μs，可降低浪涌电流
- 有源输出放电
- 封装：
  - 3mm × 3mm 可湿性侧面 VSON (8) 封装
  - 5 引脚 TO-252，$R_{\theta JA}$ = 31.6°C/W

2 应用

- 汽车音响主机
- 混合仪表组
- 远程信息处理控制单元
- 中距离和短距离雷达
- 直流/直流转换器

3 说明

TPS785-Q1 超低压降稳压器 (LDO) 是一款小型低静态电流 LDO，可提供 1A 电流，具有出色的线路和负载瞬态性能。

凭借低输出噪声和出色的 PSRR 性能，此器件适用于功耗敏感型模拟负载。TPS785-Q1 具有 1.7V 至 6.0V 的输入电压范围和 1.2V 至 5.5V 的可调节输出电压范围，是一款灵活的后置稳压器件。它还提供 0.65V 至 5.0V 的固定输出电压，为常用电压轨供电。

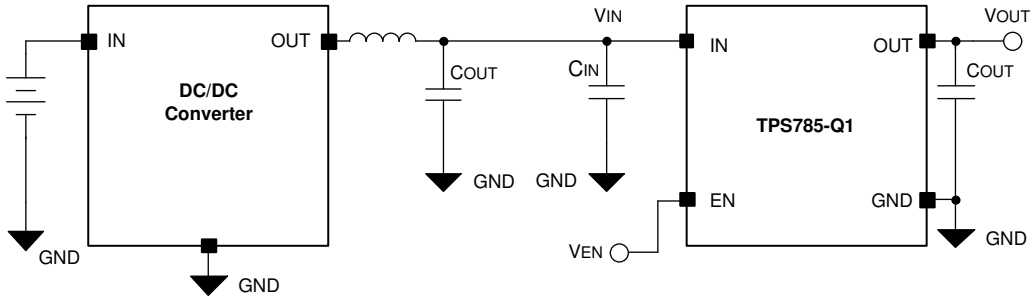
TPS785-Q1 具有折返电流限制，可在过流条件下降低功率耗散。EN 端输入有助于满足该系统的电源时序要求。内部软启动通过控制启动过程来降低浪涌电流，从而减小使用的输入电容。

TPS785-Q1 提供了有源下拉电路，当被禁用时可以使输出负载快速放电。

器件信息(1)

器件型号	封装	封装尺寸（标称值）
TPS785-Q1	可湿性侧面 VSON (8)	3.00mm x 3.00mm
	TO-252 (5)	6.10mm x 6.60mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



典型应用电路

本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。TI 不保证翻译的准确性和有效性。在实际设计之前，请务必参考最新版本的英文版本。

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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (January 2021) to Revision A (April 2021)	Page
• 将文档状态从预告信息更改为量产数据	1

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5 Pin Configuration and Functions

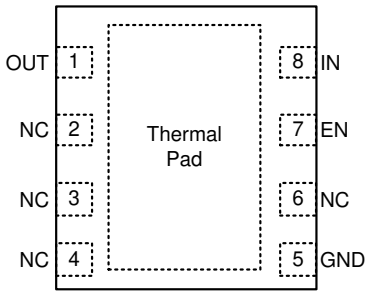

图 5-1. DRB Package (Fixed), 8-Pin VSON, Top View

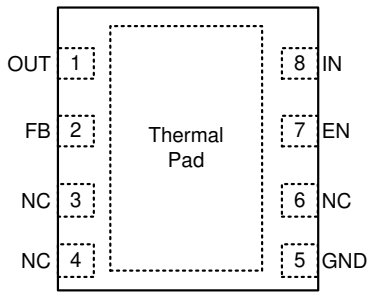

图 5-2. DRB Package (Adjustable), 8-Pin VSON, Top View

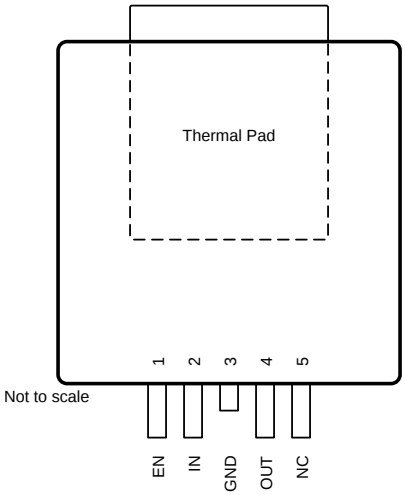

图 5-3. KVU Package (Fixed), 5-Pin TO-252, Top View

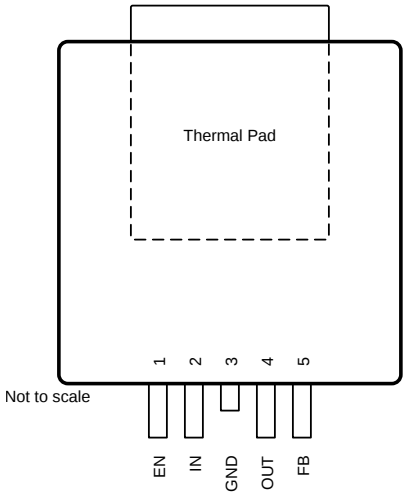

图 5-4. KVU Package (Adjustable), 5-Pin TO-252, Top View

表 5-1. Pin Functions

PIN					I/O	DESCRIPTION
NAME	DRB (Fixed)	DRB (Adjustable)	KVU (Fixed)	KVU (Adjustable)		
EN	7	7	1	1	Input	Enable pin. Driving this pin to logic high enables the device; driving this pin to logic low disables the device. Do not float this pin. If not used, connect EN to IN.
FB	—	2	—	5	Input	Feedback pin. Input to the control-loop error amplifier. This pin is used to set the output voltage of the device with the use of external resistors. Do not float this pin. For adjustable-voltage version devices only.
GND	5	5	3	3	—	Ground pin. This pin must be connected to ground on the board.
IN	8	8	2	2	Input	Input pin. For best performance, place the nominal recommended value or larger ceramic capacitor from IN to GND; see the *Recommended Operating Conditions* table. Place the input capacitor as close to the input of the device as possible.
NC	2, 3, 4, 6	3, 4, 6	5	—	—	No connect pin. This pin is not internally connected. Connect to ground for best thermal performance or leave floating.
OUT	1	1	4	4	Output	A 0.47-µF or greater effective capacitance is required from OUT to ground for stability. For best transient response, use a 1-µF or larger ceramic capacitor from OUT to ground. Place the output capacitor as close to output of the device as possible; see the *Recommended Operating Conditions* table.

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表 5-1. Pin Functions (continued)

PIN					I/O	DESCRIPTION
NAME	DRB (Fixed)	DRB (Adjustable)	KVU (Fixed)	KVU (Adjustable)		
Thermal Pad	Pad	Pad	Pad	Pad	—	The thermal pad is electrically connected to the GND pin. Connect the thermal pad to a large-area GND plane for improved thermal performance.

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Voltage	Supply, V_{IN}	–0.3	6.5	V
	Enable, V_{EN}	–0.3	6.5	V
	Output, V_{OUT}	–0.3	V_{IN} + 0.3(2)	V
	Feedback, V_{FB}	–0.3	2	V
Current	Output, I_{OUT}	Internally limited		
Temperature	Operating junction, T_J	–40	150	°C
	Storage, T_{stg}	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The absolute maximum rating is V_{IN} + 0.3 V or 6.5 V, whichever is smaller.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002(1)	±2000	V
		Charged-device model (CDM), per AEC Q100-011	±500	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

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6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V_{IN}	Input voltage		1.7		6.0	V
V_{OUT}	Output voltage	Adjustable output	1.2		5.5	V
		Fixed output	0.65		5.0	
C_{IN}	Input capacitor		0.1	1		µF
C_{OUT}	Output capacitor		1(1)		200	µF
C_{FF}	Feed-forward capacitor(2)		0	10	100	nF
I_{OUT}	Output current		0		1	A
$C_{OUT,ESR}$	Output capacitor ESR		0.001		1	Ω
V_{EN}	Enable voltage		0		6	V
F_{EN}	Enable toggle frequency				10	kHz
T_J	Junction temperature		–40		150	°C

(1) The minimum effective capacitance is 0.47 µF.
(2) Feed-forward capacitor is optional and not required for stability.

6.4 Thermal Information

THERMAL METRIC(1)		TPS785-Q1		UNIT
		DRB (VSON)	KVU (TO-252)	
		8 PINS	5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	59.5	31.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	67	40.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	31.4	10.4	°C/W
ψ_{JT}	Junction-to-top characterization parameter	3.5	4.6	°C/W
ψ_{JB}	Junction-to-board characterization parameter	31.3	10.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	15.7	3.3	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

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6.5 Electrical Characteristics

at operating temperature range (T_J = –40°C to +150°C), V_{IN} = $V_{OUT(nom)}$ + 0.75 V or 2.0 V (whichever is greater), I_{OUT} = 1 mA, V_{EN} = V_{IN}, and C_{IN} = C_{OUT} = 1 µF, unless otherwise noted. All typical values at T_J = 25°C.

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{IN}	Input voltage			1.7		6.0	V
V_{OUT}	Output voltage	Adjustable output		1.2		5.5	V
		Fixed output		0.65		5.0	
V_{OUT}	Output accuracy(5) (1)	1 mA ≤ I_{OUT} ≤ 1 A, $V_{OUT(nom)}$ + 0.75 V or 2.0 V (whichever is greater) ≤ V_{IN} ≤ 6.0 V	T_J = 25°C	–0.5		0.5	%
			–40°C ≤ T_J ≤ 85°C	–1		1	
			–40°C ≤ T_J ≤ 150°C	–1.7		1.7	
V_{OUT}	Line regulation	$V_{OUT(nom)}$ + 0.75 V or 2.0 V (whichever is greater) ≤ V_{IN} ≤ 6.0 V			0.3		mV
V_{OUT}	Load regulation	0.1 mA ≤ I_{OUT} ≤ 1 A	–40°C ≤ T_J ≤ 85°C	–7.5		7.5	mV
		0.1 mA ≤ I_{OUT} ≤ 1 A, –40°C ≤ T_J ≤ 150°C	V_{OUT} ≤ 3.3 V	–7.5		15	
			V_{OUT} > 3.3 V	–7.5		20	
ΔV_{OUT}	Load transient response settling time(2) (3)	t_R = t_F = 1 µs, C_{OUT} = 10 µF	I_{OUT} = 300 mA to 700 mA			10	µs
	Load transient response overshoot, undershoot (3) (6)		I_{OUT} = 300 mA to 700 mA	–2%			%V_{OUT}
			I_{OUT} = 700 mA to 300 mA			10%	%V_{OUT}
			I_{OUT} = 0 mA to 1000 mA	–10%			%V_{OUT}
I_{GND}	Ground current	I_{OUT} = 0 mA $V_{OUT(nom)}$ + 0.5 V or 2.0 V (whichever is greater) ≤ V_{IN} ≤ 6.0 V	T_J = 25°C	15	25	33	µA
			–40°C ≤ T_J ≤ 85°C			35	µA
			–40°C ≤ T_J ≤ 150°C			40	µA
		I_{OUT} = 500 µA $V_{OUT(nom)}$ + 0.5 V or 2.0 V (whichever is greater) ≤ V_{IN} ≤ 6.0 V	T_J = 25°C		33	44	µA
			–40°C ≤ T_J ≤ 85°C			47	µA
			–40°C ≤ T_J ≤ 150°C			50	µA
		I_{OUT} = 100 µA $V_{OUT(nom)}$ + 0.5 V or 2.0 V (whichever is greater) ≤ V_{IN} ≤ 6.0 V	–40°C ≤ T_J ≤ 85°C			45	µA
I_{SHDN}	Shutdown current	V_{EN} ≤ 0.3 V $V_{OUT(nom)}$ + 0.5 V or 2.0 V (whichever is greater) ≤ V_{IN} ≤ 6.0 V	T_J = 25°C		0.01	0.05	µA
			–40°C ≤ T_J ≤ 85°C			0.25	
			–40°C ≤ T_J ≤ 150°C			3	
V_{FB}	Feedback voltage	Adjustable output only		1.182	1.2	1.218	V
I_{FB}	Feedback pin current	Adjustable output only		–0.05	0.01	0.05	µA
I_{CL}	Output current limit	V_{IN} = $V_{OUT(nom)}$ + 1.25 V or 2.0 V (whichever is greater), V_{OUT} = 0.9 x $V_{OUT(nom)}$ (4)		1.04		1.65	A
I_{SC}	Short-circuit current limit	V_{OUT} = 0 V			550		mA

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6.5 Electrical Characteristics (continued)

at operating temperature range (T_J = –40°C to +150°C), V_{IN} = $V_{OUT(nom)}$ + 0.75 V or 2.0 V (whichever is greater), I_{OUT} = 1 mA, V_{EN} = V_{IN}, and C_{IN} = C_{OUT} = 1 µF, unless otherwise noted. All typical values at T_J = 25°C.

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{DO}	Dropout voltage (DRB package)	I_{OUT} = 1 A, V_{OUT} = 0.95 x $V_{OUT(nom)}$	0.65 V ⩽ V_{OUT} < 0.8 V			1130	mV
			0.8 V ⩽ V_{OUT} < 1.0 V			960	
			1.0 V ⩽ V_{OUT} < 1.2 V			800	
			1.2 V ⩽ V_{OUT} < 1.5 V			725	
			1.5 V ⩽ V_{OUT} < 1.8 V			500	
			1.8 V ⩽ V_{OUT} < 2.5 V			425	
			2.5 V ⩽ V_{OUT} < 3.3 V			350	
			3.3 V ⩽ V_{OUT} ⩽ 5.5 V			315	
	Dropout voltage (KVU package)	I_{OUT} = 1 A, V_{OUT} = 0.95 x $V_{OUT(nom)}$	0.65 V ⩽ V_{OUT} < 0.8 V			1225	
			0.8 V ⩽ V_{OUT} < 1.0 V			1070	
			1.0 V ⩽ V_{OUT} < 1.2 V			915	
			1.2 V ⩽ V_{OUT} < 1.5 V			755	
			1.5 V ⩽ V_{OUT} < 1.8 V			605	
			1.8 V ⩽ V_{OUT} < 2.5 V			540	
			2.5 V ⩽ V_{OUT} < 3.3 V			455	
			3.3 V ⩽ V_{OUT} ⩽ 5.5 V			425	
		I_{OUT} = 850 mA, V_{OUT} = 0.95 x $V_{OUT(nom)}$	V_{OUT} = 1.8 V			500	
		I_{OUT} = 500 mA, V_{OUT} = 0.95 x $V_{OUT(nom)}$	V_{OUT} = 1.2 V			500	
PSRR	Power-supply rejection ratio	I_{OUT} = 1 A, V_{IN} = V_{OUT} + 1 V	f = 1 kHz		60		dB
			f = 100 kHz		45		
			f = 1 MHz		30		
Vn	Output noise voltage	BW = 10 Hz to 100 kHz, V_{OUT} = 1.2 V			30		μV_{RMS}
V_{UVLO}	UVLO threshold	V_{IN} rising		1.28	1.42	1.62	V
		V_{IN} falling		1.17	1.29	1.42	
$V_{UVLO(HYST)}$	UVLO hysteresis	V_{IN} hysteresis			130		mV
t_{STR}	Start-up time	From EN low-to-high transition to V_{OUT} = $V_{OUT(nom)}$ x 92%		280	550	785	µs
$V_{EN(HI)}$	EN pin logic high voltage			0.9			V
$V_{EN(LOW)}$	EN pin logic low voltage					0.3	
I_{EN}	Enable pin current	V_{IN} = V_{EN} = 6.0 V			10		nA
$R_{PULLDOWN}$	Pulldown resistance	V_{IN} = 3.3 V			100		Ω
$T_{SD(shutdown)}$	Thermal shutdown temperature	Shutdown, temperature increasing			170		°C
$T_{SD(reset)}$	Thermal shutdown reset temperature	Reset, temperature decreasing			155		

(1) Resistor tolerance is not included in overall accuracy in the adjustable version.
(2) The settling time is measured from when I_{OUT} is stepped from 300 mA to 700 mA to when the output voltage recovers to V_{OUT} = $V_{OUT(nom)}$ - 5 mV.
(3) This specification is verified by design.
(4) The output is being forced to 90% of the nominal V_{OUT} value.
(5) Based on ambient temperature power dissipation should be limited to avoid thermal shutdown.
(6) This specification is in relation to the change from the nominal output voltage ($V_{OUT(nom)}$).

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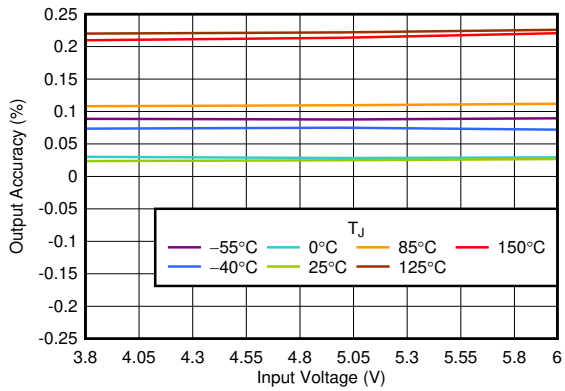
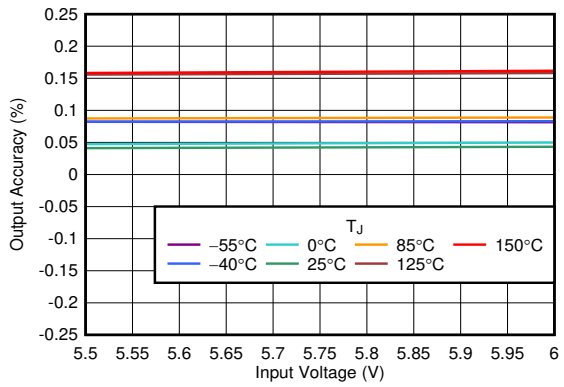
6.6 Typical Characteristics

at operating temperature T_J = 25°C, I_{OUT} = 1 mA, V_{EN} = 1.0 V, C_{IN} = 1.0 µF, C_{OUT} = 1.0 µF, and V_{IN} = $V_{OUT(NOM)}$ + 0.75 V or 1.7 V (whichever is greater), unless otherwise noted; typical values are at T_J = 25°C



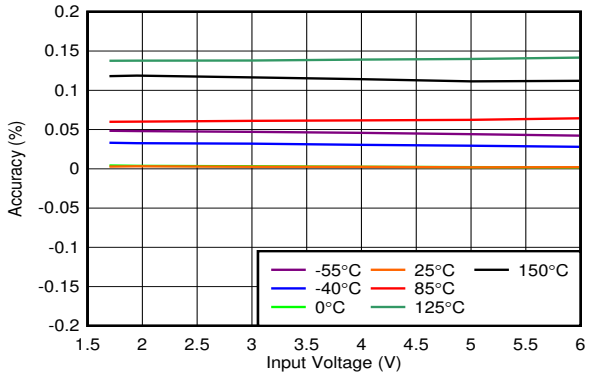
V_{OUT} = 3.3 V

图 6-1. Output Accuracy vs V_{IN}



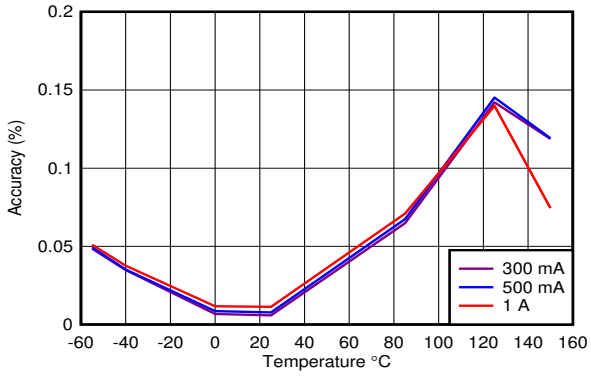
V_{OUT} = 5.0 V

图 6-2. Output Accuracy vs V_{IN}



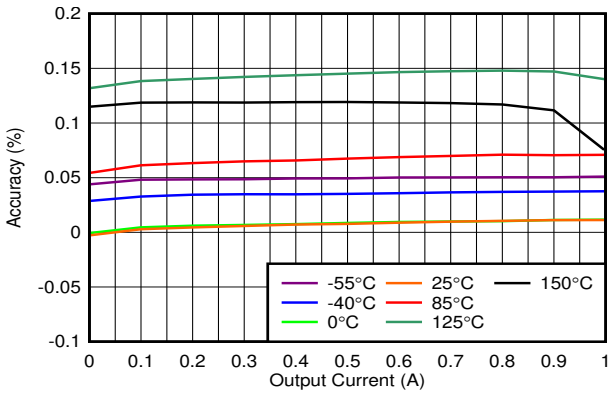
I_{OUT} = 50 mA, V_{OUT} = 1.2 V

图 6-3. Output Accuracy vs V_{IN}



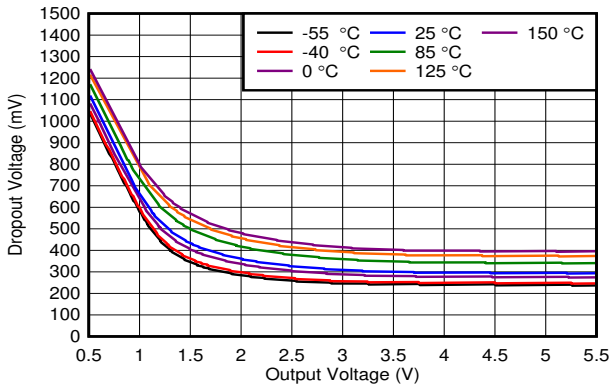
V_{OUT} = 1.2 V

图 6-4. Output Accuracy vs Temperature



V_{OUT} = 1.2 V

图 6-5. Output Accuracy vs Output Current



I_{OUT} = 1 A

图 6-6. Dropout vs Output Voltage

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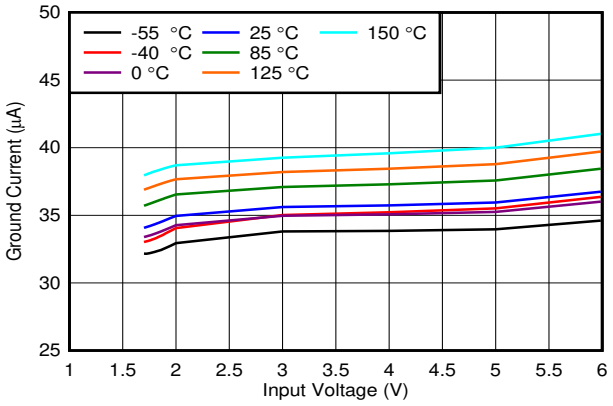
6.6 Typical Characteristics (continued)

at operating temperature T_J = 25°C, I_{OUT} = 1 mA, V_{EN} = 1.0 V, C_{IN} = 1.0 µF, C_{OUT} = 1.0 µF, and V_{IN} = $V_{OUT(NOM)}$ + 0.75 V or 1.7 V (whichever is greater), unless otherwise noted; typical values are at T_J = 25°C



I_{OUT} = 500 µA

图 6-7. I_{GND} vs V_{IN}

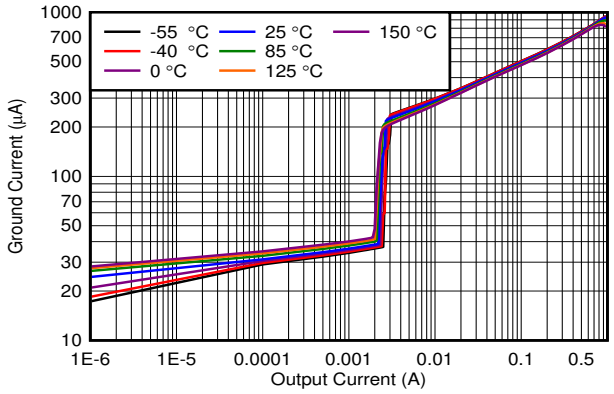
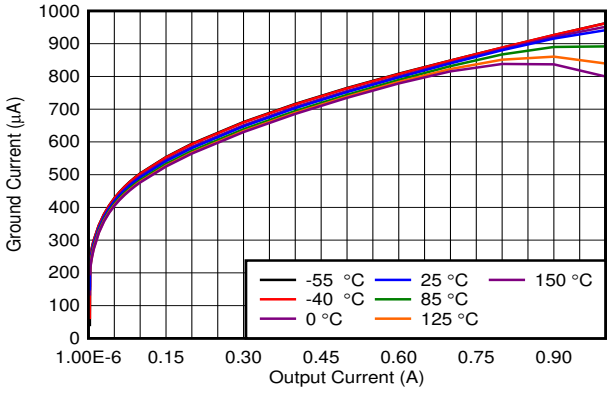
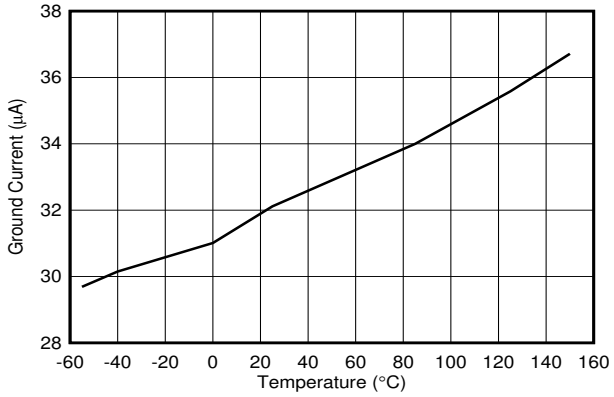


图 6-8. I_{GND} vs I_{OUT}



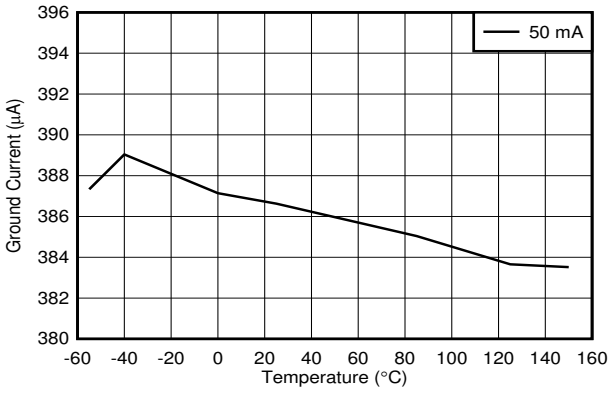
V_{OUT} = 1.2 V, V_{IN} = 2 V

图 6-9. I_{GND} vs I_{OUT}



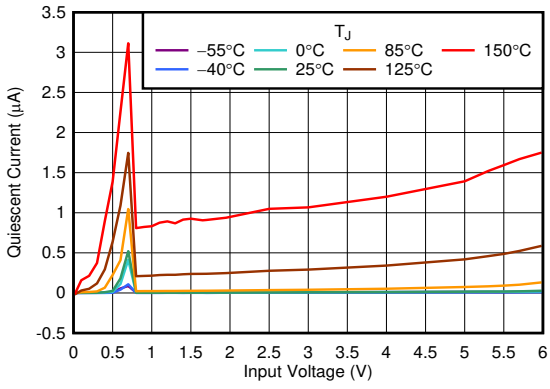
I_{OUT} = 500 µA

图 6-10. 500-µA Ground Current vs Temperature



I_{OUT} = 50 mA

图 6-11. 50-mA Ground Current vs Temperature



V_{EN} = 0.3 V

图 6-12. I_{SHDN} vs V_{IN}

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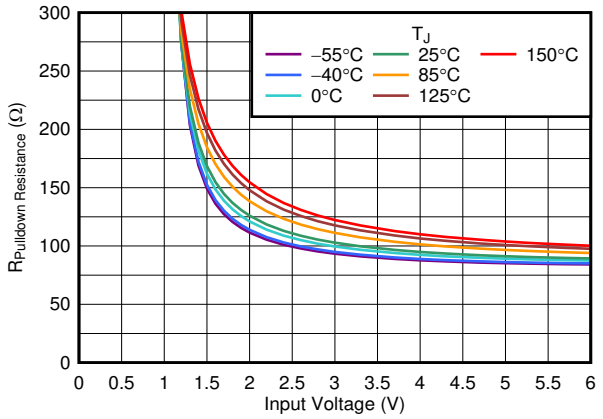
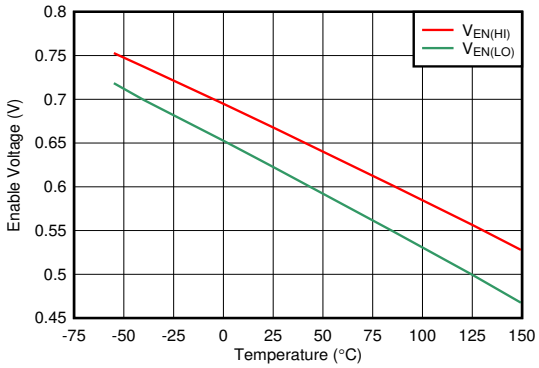
6.6 Typical Characteristics (continued)

at operating temperature T_J = 25°C, I_{OUT} = 1 mA, V_{EN} = 1.0 V, C_{IN} = 1.0 µF, C_{OUT} = 1.0 µF, and V_{IN} = $V_{OUT(NOM)}$ + 0.75 V or 1.7 V (whichever is greater), unless otherwise noted; typical values are at T_J = 25°C



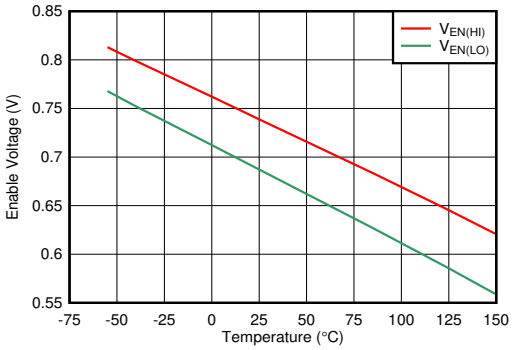
V_{EN} = 0.3 V

图 6-13. Pulldown Resistor ($R_{Pulldown}$) vs V_{IN}



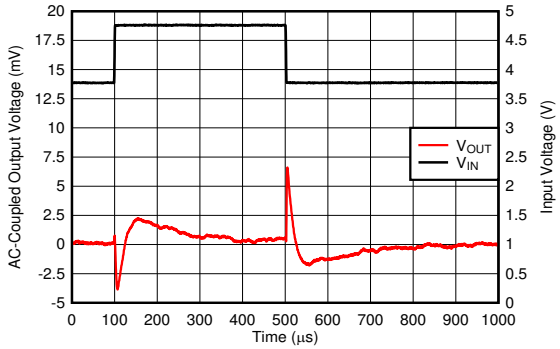
V_{IN} = 2 V

图 6-14. $V_{EN(HI)}$ and $V_{EN(LOW)}$ Thresholds vs Temperature



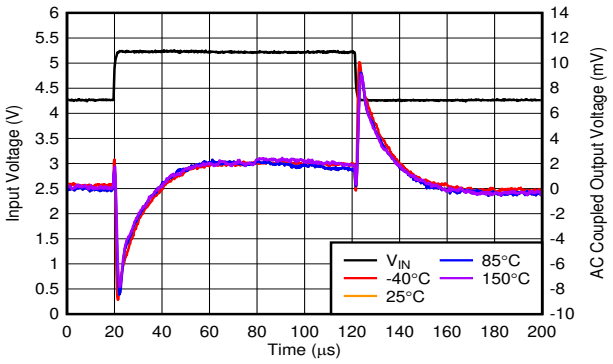
V_{IN} = 6 V

图 6-15. $V_{EN(HI)}$ and $V_{EN(LOW)}$ Thresholds vs Temperature



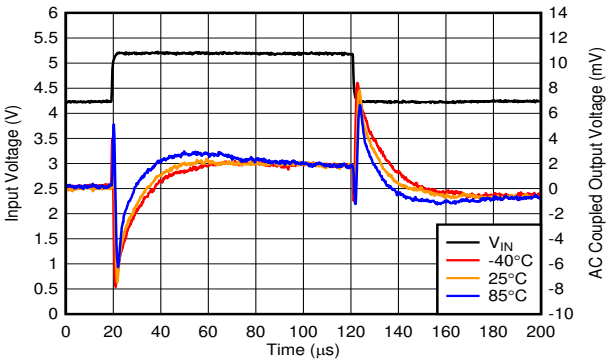
V_{OUT} = 3.3 V, I_{OUT} = 1 mA, slew rate = 1 V/µs

图 6-16. Line Transient



V_{OUT} = 3.3 V, I_{OUT} = 300 mA, slew rate = 1 V/µs

图 6-17. Line Transient vs Temperature



V_{OUT} = 3.3 V, I_{OUT} = 1 A, slew rate = 1 V/µs

图 6-18. Line Transient vs Temperature

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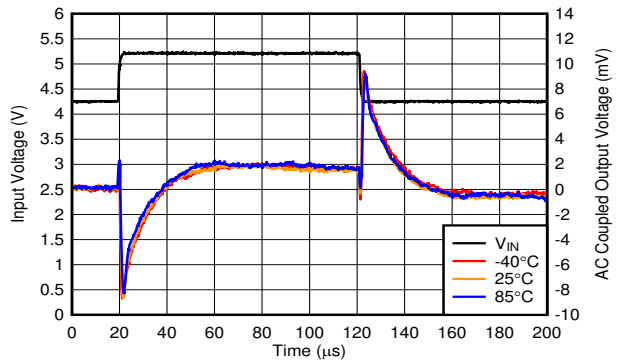
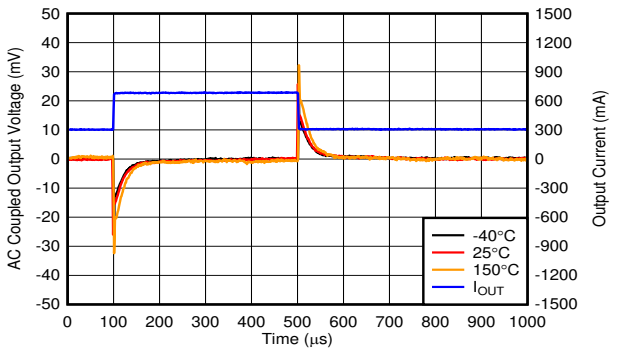
6.6 Typical Characteristics (continued)

at operating temperature T_J = 25°C, I_{OUT} = 1 mA, V_{EN} = 1.0 V, C_{IN} = 1.0 µF, C_{OUT} = 1.0 µF, and V_{IN} = $V_{OUT(NOM)}$ + 0.75 V or 1.7 V (whichever is greater), unless otherwise noted; typical values are at T_J = 25°C



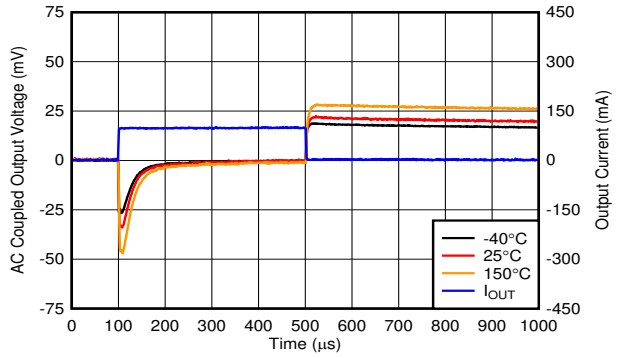
V_{OUT} = 3.3 V, I_{OUT} = 500 mA, slew rate = 1 V/µs

图 6-19. Line Transient vs Temperature



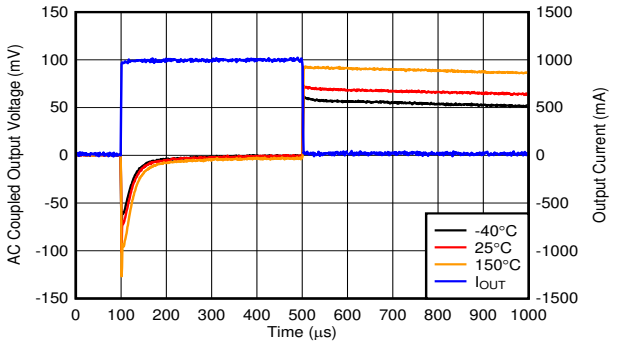
V_{OUT} = 3.3 V, I_{OUT} = 300 mA to 700 mA, rise time = 1 µs

图 6-20. Load Transient vs Temperature



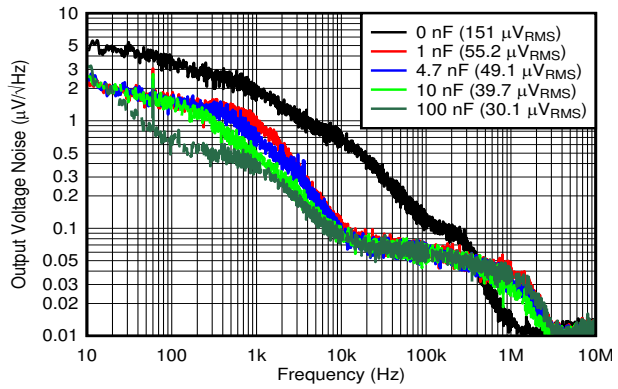
V_{OUT} = 3.3 V, I_{OUT} = 0 mA to 100 mA, rise time = 1 µs

图 6-21. Load Transient vs Temperature



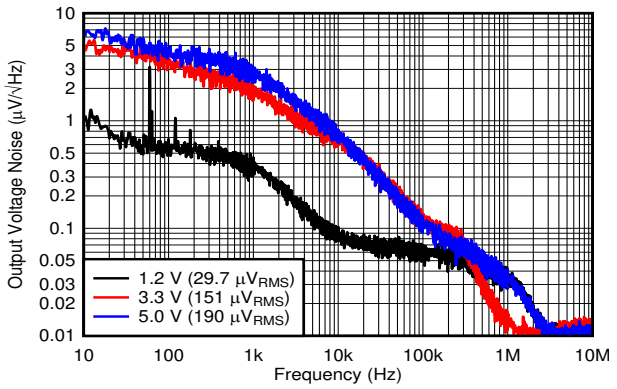
V_{OUT} = 3.3 V, I_{OUT} = 0 mA to 1 A, rise time = 1 µs

图 6-22. Load Transient vs Temperature



V_{OUT} = 3.3 V, I_{OUT} = 1 A

图 6-23. Noise vs C_{FF}



I_{OUT} = 1 A

图 6-24. Noise vs V_{OUT}

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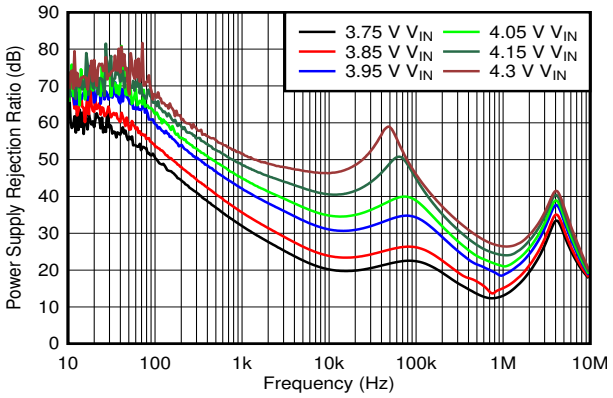
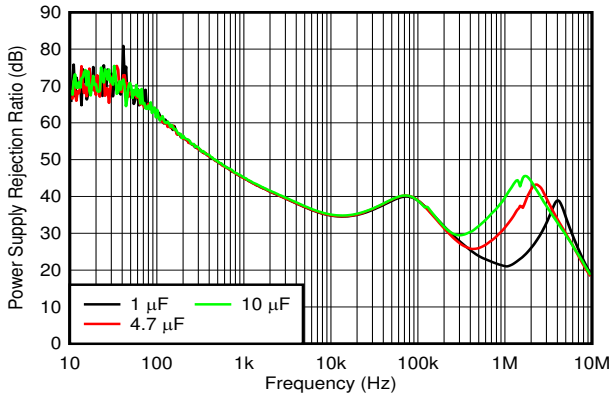
6.6 Typical Characteristics (continued)

at operating temperature T_J = 25°C, I_{OUT} = 1 mA, V_{EN} = 1.0 V, C_{IN} = 1.0 µF, C_{OUT} = 1.0 µF, and V_{IN} = $V_{OUT(NOM)}$ + 0.75 V or 1.7 V (whichever is greater), unless otherwise noted; typical values are at T_J = 25°C



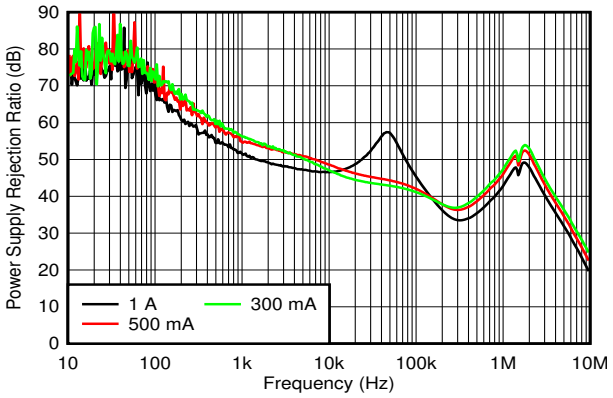
V_{OUT} = 3.3 V, I_{OUT} = 1 A

图 6-25. PSRR vs V_{IN}



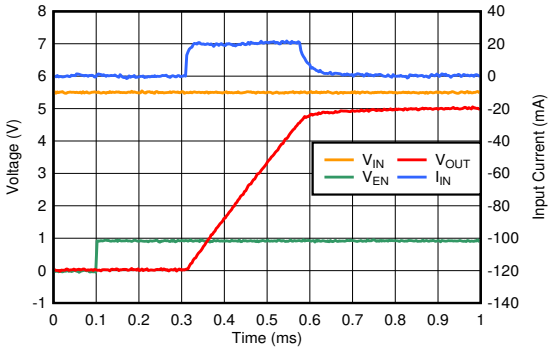
V_{OUT} = 3.3 V, I_{OUT} = 1 A

图 6-26. PSRR vs C_{OUT}



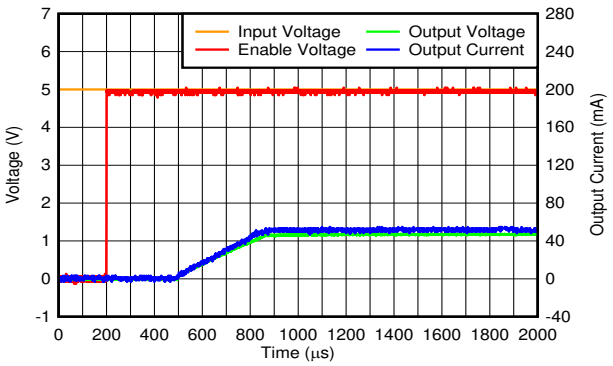
V_{OUT} = 3.3 V

图 6-27. PSRR vs I_{OUT}



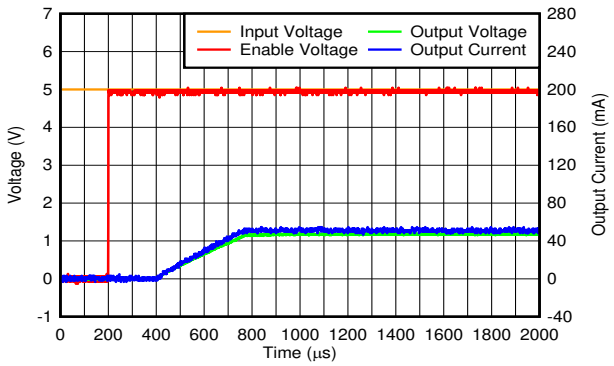
V_{IN} = 5.5 V, C_{IN} = 0 µF, C_{OUT} = 1 µF, V_{OUT} = 5.0 V, I_{OUT} = 0 mA

图 6-28. Start-Up Inrush Current With C_{OUT} = 1 µF



V_{IN} = V_{EN} = 5.5 V, C_{IN} = 0 µF, C_{OUT} = 1 µF, V_{OUT} = 1.2 V, I_{OUT} = 50 mA, T_A = -40°C

图 6-29. Start Up



V_{IN} = V_{EN} = 5.5 V, C_{IN} = 0 µF, C_{OUT} = 1 µF, V_{OUT} = 1.2 V, I_{OUT} = 50 mA, T_A = 25°C

图 6-30. Start Up

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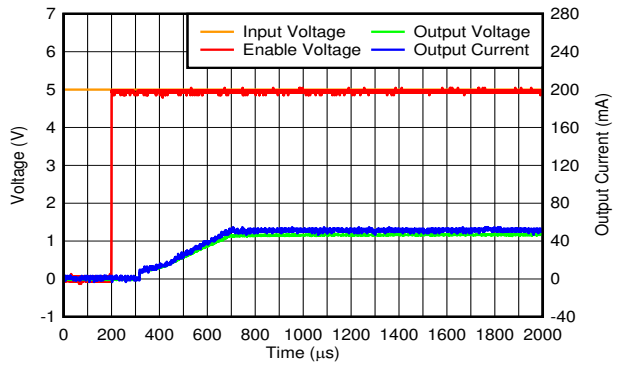
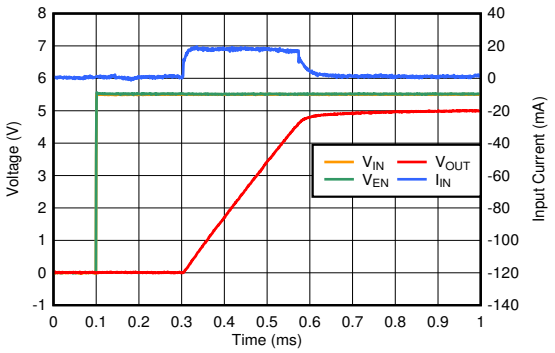
6.6 Typical Characteristics (continued)

at operating temperature T_J = 25°C, I_{OUT} = 1 mA, V_{EN} = 1.0 V, C_{IN} = 1.0 µF, C_{OUT} = 1.0 µF, and V_{IN} = $V_{OUT(NOM)}$ + 0.75 V or 1.7 V (whichever is greater), unless otherwise noted; typical values are at T_J = 25°C



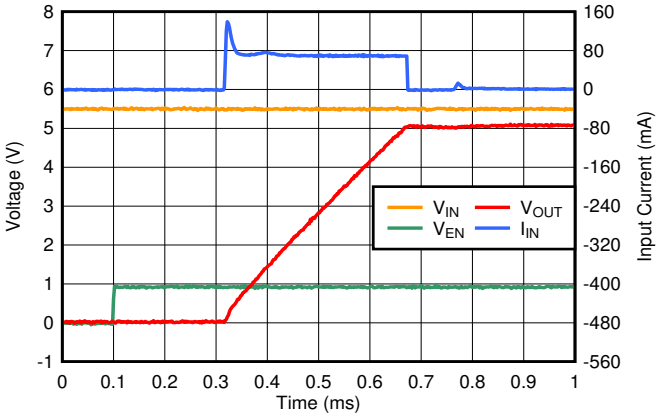
V_{IN} = V_{EN} = 5.5 V, C_{IN} = 0 µF, C_{OUT} = 1 µF, V_{OUT} = 1.2 V, I_{OUT} = 50 mA, T_A = 150°C

图 6-31. Start Up



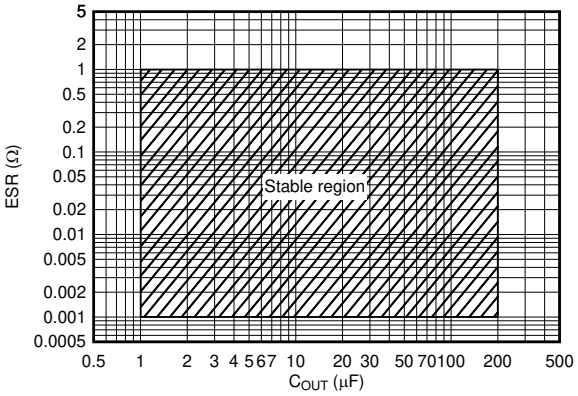
V_{IN} = V_{EN} = 5.5 V, C_{IN} = 0 µF, C_{OUT} = 1 µF, V_{OUT} = 5.0 V, I_{OUT} = 0 mA

图 6-32. Start-Up Inrush Current With C_{OUT} = 1 µF



V_{IN} = 5.5 V, C_{IN} = 0 µF, C_{OUT} = 4.7 µF, V_{OUT} = 5.0 V, I_{OUT} = 0 mA

图 6-33. Start-Up Inrush Current With C_{OUT} = 4.7 µF



C_{OUT} denotes nominal capacitor size (not effective capacitance)

图 6-34. ESR vs C_{OUT}

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7 Detailed Description

7.1 Overview

The TPS785-Q1 is an ultra low-dropout, high PSRR, high-accuracy linear voltage regulator that is optimized for excellent transient performance. These characteristics make the device ideal for most automotive applications.

This regulator offers foldback current limit, output enable, active discharge, undervoltage lockout (UVLO), and thermal protection.

7.2 Functional Block Diagrams

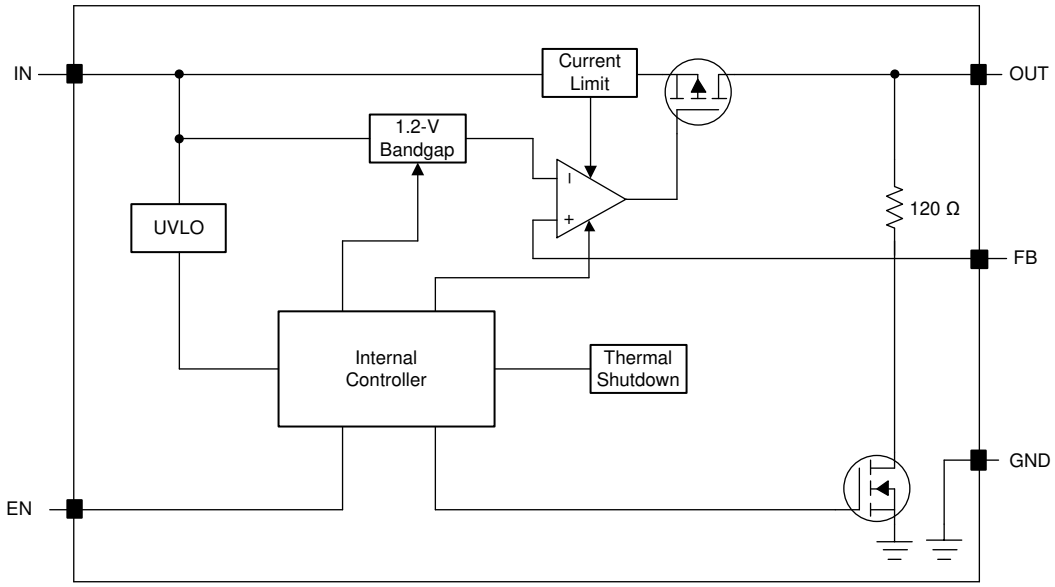

图 7-1. Adjustable Version Block Diagram

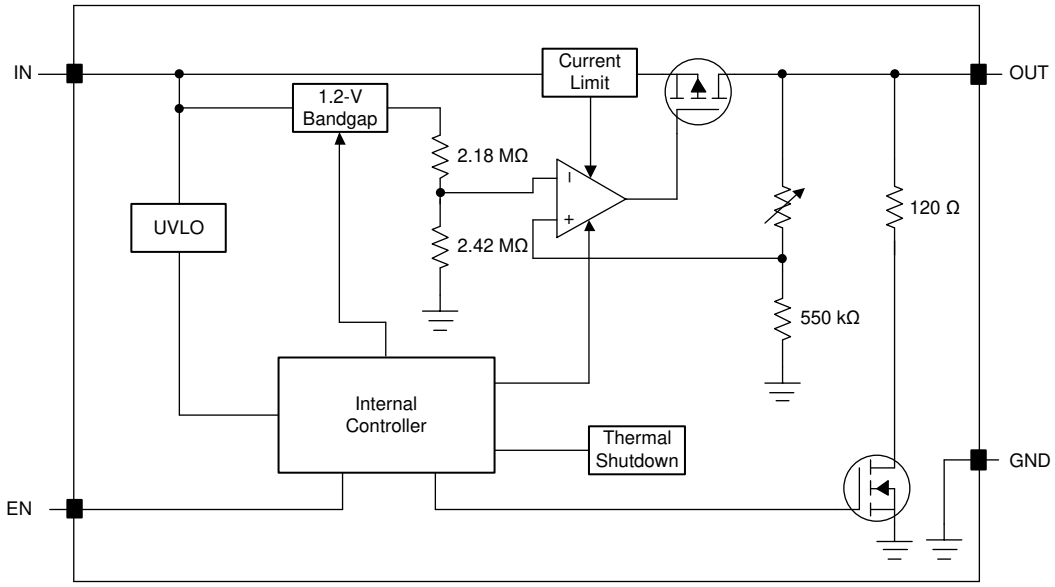

图 7-2. Fixed Version Block Diagram

7.3 Feature Description

7.3.1 Foldback Current Limit

The device has an internal current limit circuit that protects the regulator during transient high-load current faults or shorting events. The current limit is a hybrid brickwall-foldback scheme. The current limit transitions from a brickwall scheme to a foldback scheme at the foldback voltage ($V_{FOLDBACK}$). In a high-load current fault with the output voltage above $V_{FOLDBACK}$, the brickwall scheme limits the output current to the current limit (I_{CL}). When the voltage drops below $V_{FOLDBACK}$, a foldback current limit activates that scales back the current as the output voltage approaches GND. When the output is shorted, the device supplies a typical current called the short-circuit current limit (I_{SC}). I_{CL} and I_{SC} are listed in the *Electrical Characteristics* table.

For this device, $V_{FOLDBACK} = 0.4 \times V_{OUT(NOM)}$.

The output voltage is not regulated when the device is in current limit. When a current limit event occurs, the device begins to heat up because of the increase in power dissipation. When the device is in brickwall current limit, the pass transistor dissipates power [(V_{IN} – V_{OUT}) × I_{CL}]. When the device output is shorted and the output is below $V_{FOLDBACK}$, the pass transistor dissipates power [(V_{IN} – V_{OUT}) × I_{SC}]. If thermal shutdown is triggered, the device turns off. After the device cools down, the internal thermal shutdown circuit turns the device back on. If the output current fault condition continues, the device cycles between current limit and thermal shutdown. For more information on current limits, see the *Know Your Limits* application report.

图 7-3 shows a diagram of the foldback current limit.

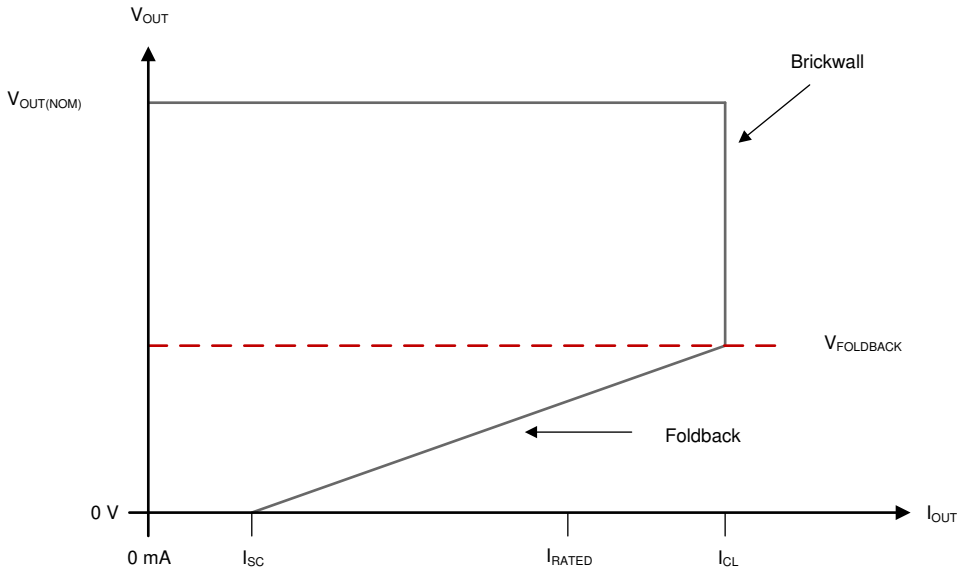

图 7-3. Foldback Current Limit

7.3.2 Output Enable

The enable pin (EN) is active high. Enable the device by forcing the voltage of the enable pin to exceed the minimum EN pin high-level input voltage (see the *Electrical Characteristics* table). Turn off the device by forcing the voltage of the enable pin to drop below the maximum EN pin low-level input voltage (see the *Electrical Characteristics* table). If shutdown capability is not required, connect EN to IN.

This device has an internal pulldown circuit that activates when the device is disabled to actively discharge the output voltage.

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7.3.3 Active Discharge

The device has an internal pulldown MOSFET that connects an $R_{PULLDOWN}$ resistor to ground when the device is disabled to actively discharge the output voltage. The active discharge circuit is activated by the enable pin.

Do not rely on the active discharge circuit to discharge the output voltage after the input supply has collapsed because reverse current can possibly flow from the output to the input. This reverse current flow can cause damage to the device, especially when a large output capacitor is used. Limit reverse current to no more than 5% of the device rated current for a short period of time.

7.3.4 Undervoltage Lockout (UVLO) Operation

The UVLO circuit ensures that the device stays disabled before its input supply reaches the minimum operational voltage range, and ensures that the device shuts down when the input supply collapses. 图 7-4 shows the UVLO circuit response to various input voltage events. The diagram can be separated into the following parts:

- Region A: The device does not start until the input reaches the UVLO rising threshold.
- Region B: Normal operation, regulating device.
- Region C: Brownout event above the UVLO falling threshold (UVLO rising threshold – UVLO hysteresis). The output may fall out of regulation but the device remains enabled.
- Region D: Normal operation, regulating device.
- Region E: Brownout event below the UVLO falling threshold. The device is disabled in most cases and the output falls because of the load and active discharge circuit. The device is reenabled when the UVLO rising threshold is reached by the input voltage and a normal start-up follows.
- Region F: Normal operation followed by the input falling to the UVLO falling threshold.
- Region G: The device is disabled when the input voltage falls below the UVLO falling threshold to 0 V. The output falls because of the load and active discharge circuit.

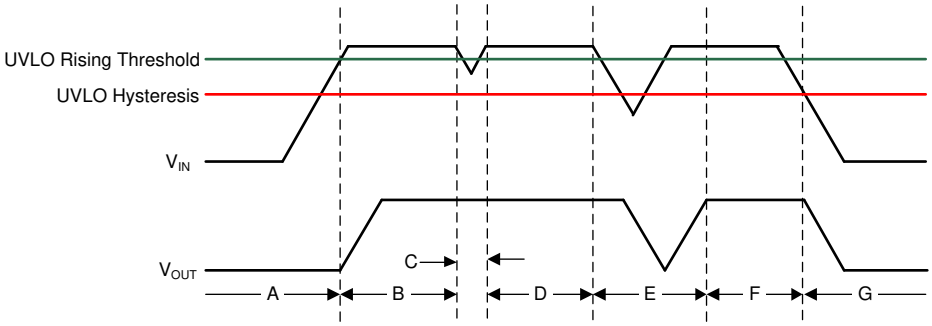

图 7-4. Typical UVLO Operation

7.3.5 Dropout Voltage

Dropout voltage (V_{DO}) is defined as the input voltage minus the output voltage (V_{IN} – V_{OUT}) at the rated output current (I_{RATED}), where the pass transistor is fully on. I_{RATED} is the maximum I_{OUT} listed in the *Recommended Operating Conditions* table. The pass transistor is in the ohmic or triode region of operation, and acts as a switch. The dropout voltage indirectly specifies a minimum input voltage greater than the nominal programmed output voltage at which the output voltage is expected to stay in regulation. If the input voltage falls to less than the nominal output regulation, then the output voltage falls as well.

For a CMOS regulator, the dropout voltage is determined by the drain-source on-state resistance ($R_{DS(ON)}$) of the pass transistor. Therefore, if the linear regulator operates at less than the rated current, the dropout voltage for that current scales accordingly. The following equation calculates the $R_{DS(ON)}$ of the device.

$$R_{DS(ON)} = \frac{V_{DO}}{I_{RATED}} \quad (1)$$

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7.3.6 Thermal Shutdown

The device contains a thermal shutdown protection circuit to disable the device when the junction temperature (T_J) of the pass transistor rises to $T_{SD(shutdown)}$ (typical). Thermal shutdown hysteresis assures that the device resets (turns on) when the temperature falls to $T_{SD(reset)}$ (typical).

The thermal time-constant of the semiconductor die is fairly short, thus the device may cycle on and off when thermal shutdown is reached until power dissipation is reduced. Power dissipation during startup can be high from large V_{IN} – V_{OUT} voltage drops across the device or from high inrush currents charging large output capacitors. Under some conditions, the thermal shutdown protection disables the device before startup completes.

For reliable operation, limit the junction temperature to the maximum listed in the *Recommended Operating Conditions* table. Operation above this maximum temperature causes the device to exceed its operational specifications. Although the internal protection circuitry of the device is designed to protect against thermal overall conditions, this circuitry is not intended to replace proper heat sinking. Continuously running the device into thermal shutdown or above the maximum recommended junction temperature reduces long-term reliability.

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7.4 Device Functional Modes

7.4.1 Device Functional Mode Comparison

The *Device Functional Mode Comparison* table shows the conditions that lead to the different modes of operation. See the *Electrical Characteristics* table for parameter values.

表 7-1. Device Functional Mode Comparison

OPERATING MODE	PARAMETER			
	V_{IN}	V_{EN}	I_{OUT}	T_J
Normal operation	$V_{IN} > V_{OUT(nom)} + V_{DO}$ and $V_{IN} > V_{IN(min)}$	$V_{EN} > V_{EN(HI)}$	$I_{OUT} < I_{OUT(max)}$	$T_J < T_{SD(shutdown)}$
Dropout operation	$V_{IN(min)} < V_{IN} < V_{OUT(nom)} + V_{DO}$	$V_{EN} > V_{EN(HI)}$	$I_{OUT} < I_{OUT(max)}$	$T_J < T_{SD(shutdown)}$
Disabled (any true condition disables the device)	$V_{IN} < V_{UVLO}$	$V_{EN} < V_{EN(LOW)}$	Not applicable	$T_J > T_{SD(shutdown)}$

7.4.2 Normal Operation

The device regulates to the nominal output voltage when the following conditions are met:

- The input voltage is greater than the nominal output voltage plus the dropout voltage ($V_{OUT(nom)} + V_{DO}$)
- The output current is less than the current limit ($I_{OUT} < I_{CL}$)
- The device junction temperature is less than the thermal shutdown temperature ($T_J < T_{SD}$)
- The enable voltage has previously exceeded the enable rising threshold voltage and has not yet decreased to less than the enable falling threshold

7.4.3 Dropout Operation

If the input voltage is lower than the nominal output voltage plus the specified dropout voltage, but all other conditions are met for normal operation, the device operates in dropout mode. In this mode, the output voltage tracks the input voltage. During this mode, the transient performance of the device becomes significantly degraded because the pass transistor is in the ohmic or triode region, and acts as a switch. Line or load transients in dropout can result in large output-voltage deviations.

When the device is in a steady dropout state (defined as when the device is in dropout, $V_{IN} < V_{OUT(NOM)} + V_{DO}$, directly after being in a normal regulation state, but *not* during startup), the pass transistor is driven into the ohmic or triode region. When the input voltage returns to a value greater than or equal to the nominal output voltage plus the dropout voltage ($V_{OUT(NOM)} + V_{DO}$), the output voltage can overshoot for a short period of time while the device pulls the pass transistor back into the linear region.

7.4.4 Disabled

The output of the device can be shutdown by forcing the voltage of the enable pin to less than the maximum EN pin low-level input voltage (see the *Electrical Characteristics* table). When disabled, the pass transistor is turned off, internal circuits are shutdown, and the output voltage is actively discharged to ground by an internal discharge circuit from the output to ground.

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8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

8.1.1 Recommended Capacitor Types

The device is designed to be stable using low equivalent series resistance (ESR) ceramic capacitors at the input and output. Multilayer ceramic capacitors have become the industry standard for these types of applications and are recommended, but must be used with good judgment. Ceramic capacitors that employ X7R-, X5R-, and C0G-rated dielectric materials provide relatively good capacitive stability across temperature, whereas the use of Y5V-rated capacitors is discouraged because of large variations in capacitance.

Regardless of the ceramic capacitor type selected, the effective capacitance varies with operating voltage and temperature. As a rule of thumb, expect the effective capacitance to decrease by as much as 50%. The input and output capacitors recommended in the *Recommended Operating Conditions* table account for an effective capacitance of approximately 50% of the nominal value.

8.1.2 Input and Output Capacitor Requirements

The device requires an input capacitor of 1.0 µF or larger as specified in the *Recommended Operating Conditions* table for stability. A higher value capacitor may be necessary if large, fast rise-time load or line transients are anticipated or if the device is located several inches from the input power source.

The device also requires an output capacitor of 1.0 µF or larger as specified in the *Recommended Operating Conditions* table for stability. Dynamic performance of the device is improved by using a higher capacitor than the minimum output capacitor.

8.1.3 Adjustable Device Feedback Resistors

The device requires external feedback divider resistors to set the output voltage. 图 8-1 shows how the output voltage of an adjustable device can be configured from 1.2 V to 5.5 V by using a resistor divider network.

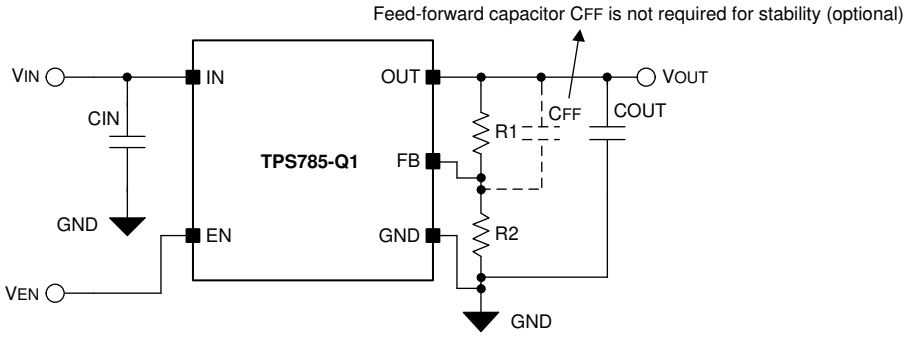

图 8-1. Adjustable Operation

方程式 2 calculates the values of the R_1 and R_2 resistors to set the output voltage:

$$V_{OUT} = V_{FB} \times (1 + R_1 / R_2) + I_{FB} \times R_1 \quad (2)$$

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To disregard the effect of the FB pin current error term in 方程式 2 and to achieve best accuracy, choose R_2 to be equal to or smaller than 550 kΩ so that the current flowing through R_1 and R_2 is at least 100 times larger than the I_{FB} current listed in the *Electrical Characteristics* table. Lowering the value of R_2 increases the immunity against noise injection. Increasing the value of R_2 reduces the quiescent current for achieving higher efficiency at low load currents. 方程式 3 calculates the setting that provides the maximum feedback divider series resistance.

$$(R_1 + R_2) \leqslant V_{OUT} / (I_{FB} \times 100) \quad (3)$$

8.1.4 Load Transient Response

The load-step transient response is the output voltage response by the LDO to a step in load current, whereby output voltage regulation is maintained. There are two key transitions during a load transient response: the transition from a light to a heavy load and the transition from a heavy to a light load. The regions shown in 图 8-2 are broken down as follows. Regions A, E, and H are where the output voltage is in steady-state.

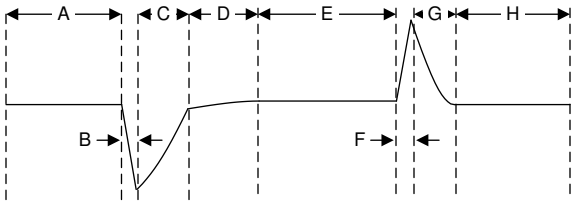

图 8-2. Load Transient Waveform

During transitions from a light load to a heavy load, the:

- Initial voltage dip is a result of the depletion of the output capacitor charge and parasitic impedance to the output capacitor (region B)
- Recovery from the dip results from the LDO increasing its sourcing current, and leads to output voltage regulation (region C)
- Initial voltage rise results from the LDO sourcing a large current, and leads to the output capacitor charge to increase (region F)
- Recovery from the rise results from the LDO decreasing its sourcing current in combination with the load discharging the output capacitor (region G)

A larger output capacitance reduces the peaks during a load transient but slows down the response time of the device. A larger DC load also reduces the peaks because the amplitude of the transition is lowered and a higher current discharge path is provided for the output capacitor.

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8.1.5 Exiting Dropout

Some applications have transients that place the LDO into dropout, such as slower ramps on V_{IN} during start-up. As with other LDOs, the output can overshoot on recovery from these conditions. A ramping input supply causes an LDO to overshoot on start-up, as shown in 图 8-3, when the slew rate and voltage levels are in the correct range. Use an enable signal to avoid this condition.

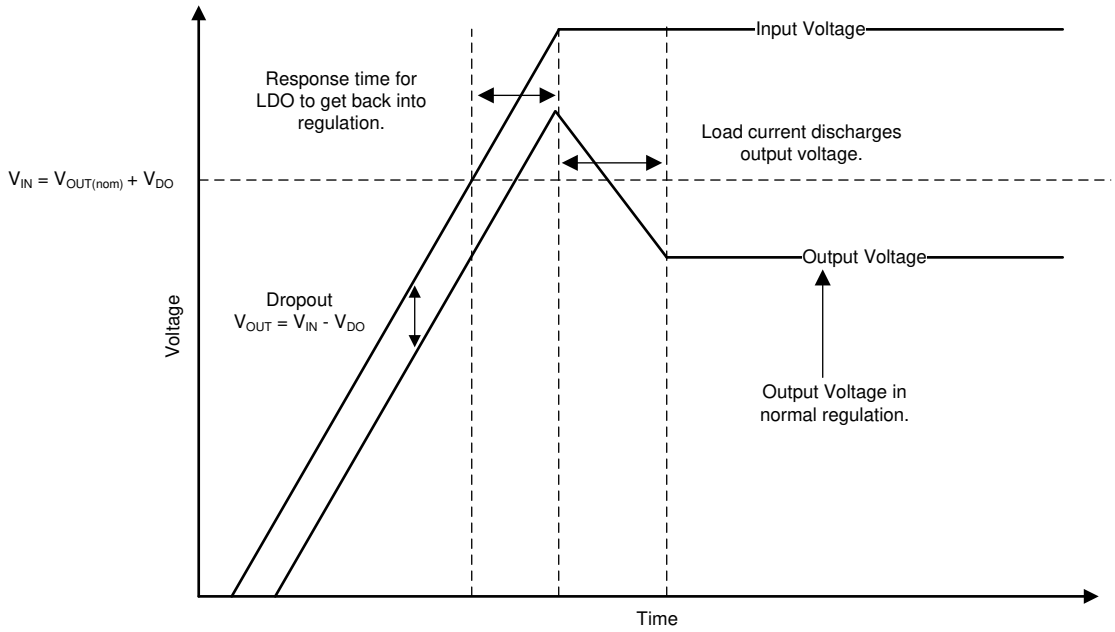

图 8-3. Start-Up Into Dropout

Line transients out of dropout can also cause overshoot on the output of the regulator. These overshoots are caused by the error amplifier having to drive the gate capacitance of the pass element and bring the gate back to the correct voltage for proper regulation. 图 8-4 illustrates what is happening internally with the gate voltage and how overshoot can be caused during operation. When the LDO is placed in dropout, the gate voltage (V_{GS}) is pulled all the way down to ground to give the pass device the lowest on-resistance as possible. However, if a line transient occurs when the device is in dropout, the loop is not in regulation and can cause the output to overshoot until the loop responds and the output current pulls the output voltage back down into regulation. If these transients are not acceptable, then continue to add input capacitance in the system until the transient is slow enough to reduce the overshoot.

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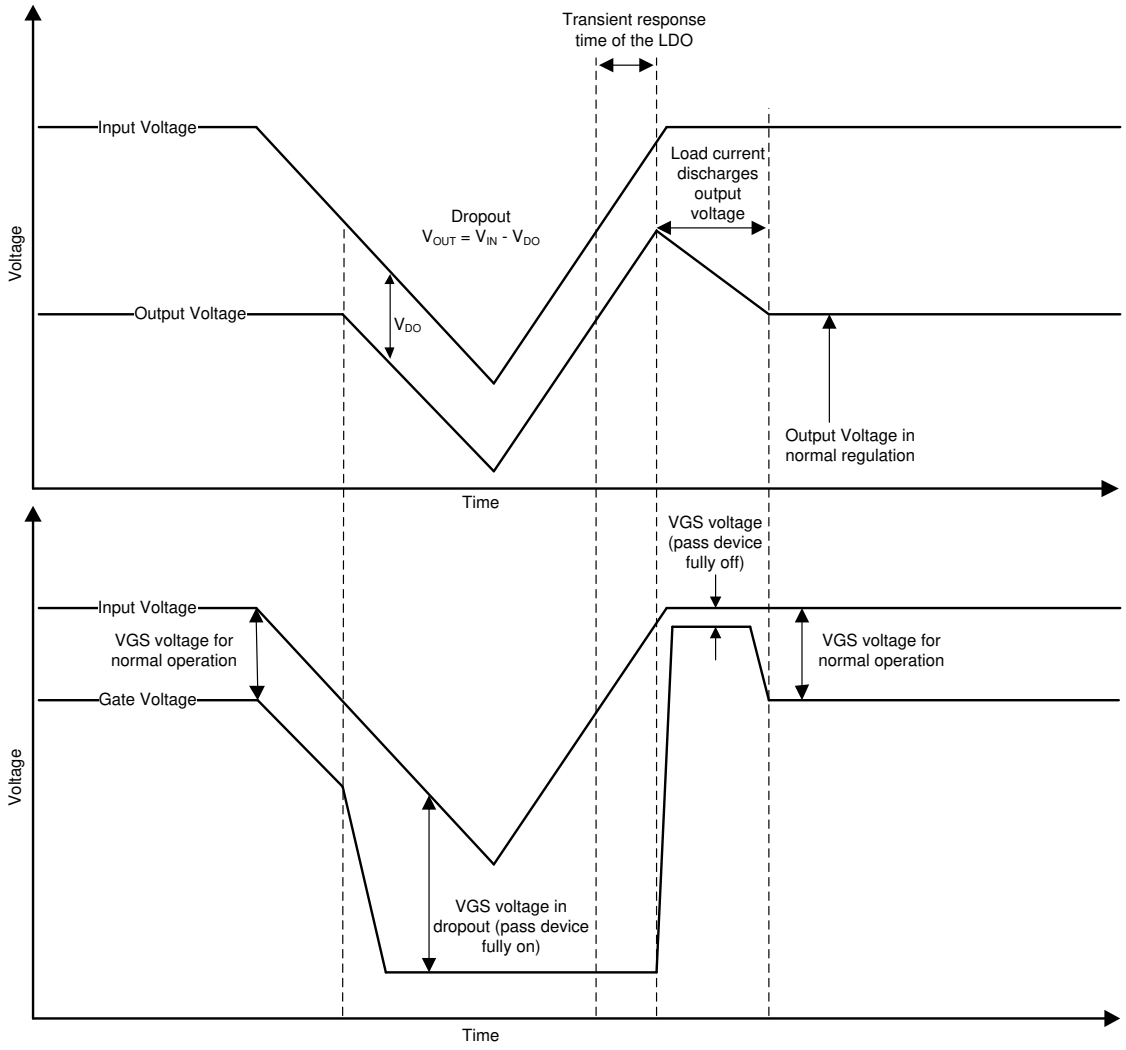

图 8-4. Line Transients From Dropout

8.1.6 Dropout Voltage

The device uses a PMOS pass transistor to achieve low dropout. When (V_{IN} – V_{OUT}) is less than the dropout voltage (V_{DO}), the PMOS pass device is in the linear region of operation and the input-to-output resistance is the $R_{DS(ON)}$ of the PMOS pass element. V_{DO} scales approximately with output current because the PMOS device behaves like a resistor in dropout mode. As with any linear regulator, PSRR and transient response degrade as (V_{IN} – V_{OUT}) approaches dropout operation.

8.1.7 Reverse Current

As with most LDOs, excessive reverse current can damage this device.

Reverse current flows through the body diode on the pass element instead of the normal conducting channel. At high magnitudes, this current flow degrades the long-term reliability of the device as a result of one of the following conditions:

- Degradation caused by electromigration
- Excessive heat dissipation
- Potential for a latch-up condition

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Conditions where reverse current can occur are outlined in this section, all of which can exceed the absolute maximum rating of $V_{OUT} > V_{IN} + 0.3$ V:

- If the device has a large C_{OUT} and the input supply collapses with little or no load current
- The output is biased when the input supply is not established
- The output is biased above the input supply

If reverse current flow is expected in the application, external protection must be used to protect the device. 图 8-5 shows one approach of protecting the device.

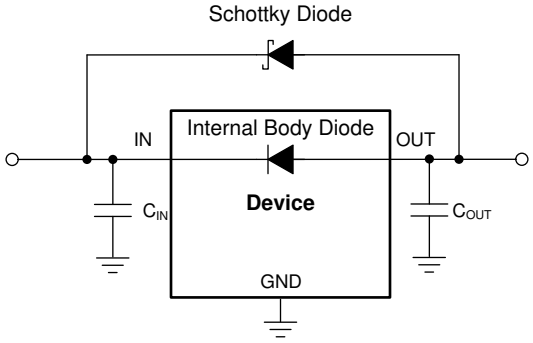

图 8-5. Example Circuit for Reverse Current Protection Using a Schottky Diode

8.1.8 Feed-Forward Capacitor (C_{FF})

For the adjustable-voltage version device, a feed-forward capacitor (C_{FF}) can be connected from the OUT pin to the FB pin. C_{FF} improves transient, noise, and PSRR performance, but is not required for regulator stability. Recommended C_{FF} values are listed in the *Recommended Operating Conditions* table. A higher capacitance C_{FF} can be used; however, the startup time increases. For a detailed description of C_{FF} tradeoffs, see the *Pros and Cons of Using a Feedforward Capacitor with a Low-Dropout Regulator* application report.

8.1.9 Power Dissipation (P_D)

Circuit reliability demands that proper consideration be given to device power dissipation, location of the circuit on the printed circuit board (PCB), and correct sizing of the thermal plane. The PCB area around the regulator must be as free as possible of other heat-generating devices that cause added thermal stresses.

As a first-order approximation, power dissipation in the regulator depends on the input-to-output voltage difference and load conditions. Use 方程式 4 to approximate P_D:

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (4)$$

Power dissipation can be minimized, and thus greater efficiency achieved, by proper selection of the system voltage rails. Proper selection allows the minimum input-to-output voltage differential to be obtained. The low dropout of the TPS785-Q1 allows for maximum efficiency across a wide range of output voltages.

The main heat conduction path for the device is through the thermal pad on the package. As such, the thermal pad must be soldered to a copper pad area under the device. This pad area contains an array of plated vias that conduct heat to any inner plane areas or to a bottom-side copper plane.

The maximum power dissipation determines the maximum allowable junction temperature (T_J) for the device. According to 方程式 5, power dissipation and junction temperature are most often related by the junction-to-ambient thermal resistance ($R_{\theta JA}$) of the combined PCB and device package and the temperature of the ambient air (T_A). 方程式 6 rearranges 方程式 5 for output current.

$$T_J = T_A + (R_{\theta JA} \times P_D) \quad (5)$$

$$I_{OUT} = (T_J - T_A) / [R_{\theta JA} \times (V_{IN} - V_{OUT})] \quad (6)$$

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Unfortunately, this thermal resistance ($R_{\theta JA}$) is highly dependent on the heat-spreading capability built into the particular PCB design, and therefore varies according to the total copper area, copper weight, and location of the planes. The $R_{\theta JA}$ recorded in the *Recommended Operating Conditions* table is determined by the JEDEC standard, PCB, and copper-spreading area, and is only used as a relative measure of package thermal performance. For a well-designed thermal layout, $R_{\theta JA}$ is actually the sum of the VSON package junction-to-case (bottom) thermal resistance ($R_{\theta JC(bot)}$) plus the thermal resistance contribution by the PCB copper.

8.1.9.1 Estimating Junction Temperature

The JEDEC standard now recommends the use of psi (Ψ) thermal metrics to estimate the junction temperatures of the LDO when in-circuit on a typical PCB board application. These metrics are not strictly speaking thermal resistances, but rather offer practical and relative means of estimating junction temperatures. These psi metrics are determined to be significantly independent of the copper-spreading area. The key thermal metrics (Ψ_{JT} and Ψ_{JB}) are used in accordance with 方程式 7 and are given in the *Recommended Operating Conditions* table.

$$\Psi_{JT} : T_J = T_T + \Psi_{JT} \times P_D \text{ and } \Psi_{JB} : T_J = T_B + \Psi_{JB} \times P_D \quad (7)$$

where:

- P_D is the power dissipated as explained in 方程式 4
- T_T is the temperature at the center-top of the device package, and
- T_B is the PCB surface temperature measured 1 mm from the device package and centered on the package edge

8.1.9.2 Recommended Area for Continuous Operation

The operational area of an LDO is limited by the dropout voltage, output current, junction temperature, and input voltage. The recommended area for continuous operation for a linear regulator is given in 图 8-6 and can be separated into the following parts:

- Dropout voltage limits the minimum differential voltage between the input and the output ($V_{IN} - V_{OUT}$) at a given output current level. See the *Dropout Voltage* section for more details.
- The rated output currents limits the maximum recommended output current level. Exceeding this rating causes the device to fall out of specification.
- The rated junction temperature limits the maximum junction temperature of the device. Exceeding this rating causes the device to fall out of specification and reduces long-term reliability.
  - The shape of the slope is given by 方程式 6. The slope is nonlinear because the maximum rated junction temperature of the LDO is controlled by the power dissipation across the LDO; thus when $V_{IN} - V_{OUT}$ increases the output current must decrease.
- The rated input voltage range governs both the minimum and maximum of $V_{IN} - V_{OUT}$.

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图 8-6 shows the recommended area of operation for this device on a JEDEC-standard high-K board with a $R_{\theta JA}$ as given in the *Recommended Operating Conditions* table.

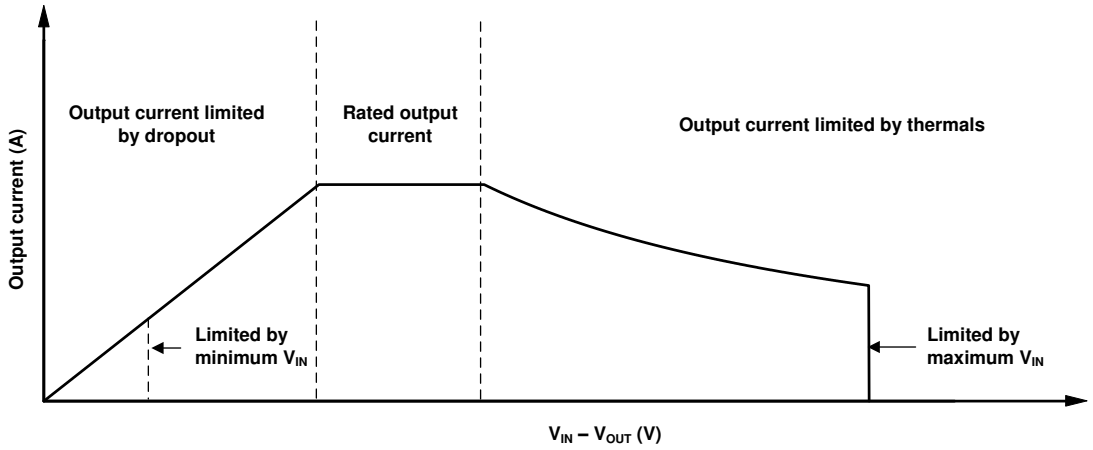

图 8-6. Region Description of Continuous Operation Regime

8.1.9.3 Power Dissipation versus Ambient Temperature

图 8-7 is based off of a JESD51-7 four-layer high-K board. The allowable power dissipation was estimated using the following equation. As disscussed in the *An empirical analysis of the impact of board layout on LDO thermal performance* application report, thermal dissipation can be improved in the JEDEC high-K layout by adding top layer copper and increasing the number of thermal vias. If a good thermal layout is used, the allowable thermal dissipation can be improved by up to 50%.

$$T_A + R_{\theta JA} \times P_D \leq 150°C \quad (8)$$

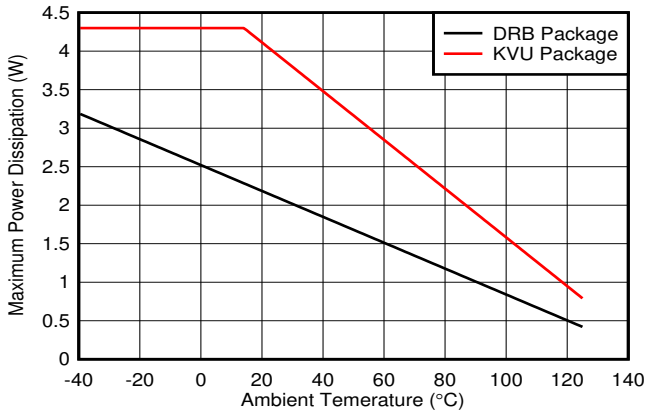

图 8-7. Allowable Power Dissipation

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8.2 Typical Application

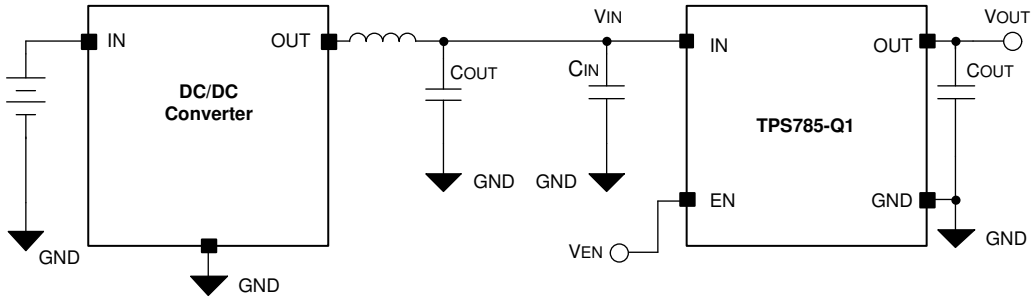


图 8-8. Operation From a DC/DC Converter

8.2.1 Design Requirements

表 8-1 summarizes the design requirement for this application.

表 8-1. Design Parameters

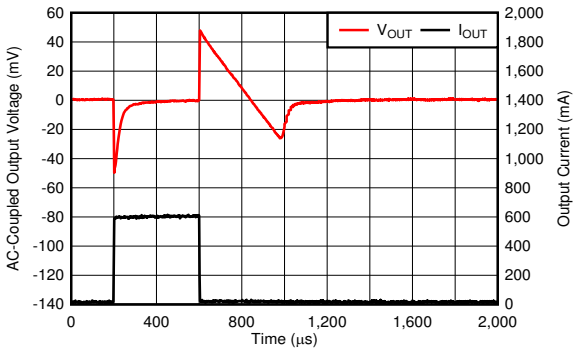
PARAMETER	DESIGN REQUIREMENT
Input voltage	4.05 V
Output voltage	3.3 V, ±1.5%
Output load	600 mA
Output capacitor	10 µF
Maximum ambient temperature	85°C

8.2.2 Detailed Design Procedure

For this design example, the 3.3-V, fixed-version device is selected. The device is powered of a DC/DC converter connected to a battery. A 750-mV headroom between V_{IN} and V_{OUT} is used to keep the device within the dropout voltage specification and to ensure the device stays in regulation under all load and temperature conditions for this design.

8.2.3 Application Curve

A 10-µF capacitor is used to reduce overshoot and undershoot of output voltage during load transients with ramps rates greater than 1 A/µs. 图 8-9 shows a capture of load transient behavior for this application.



V_{IN} = 4.05 V, V_{OUT} = 3.3 V, C_{OUT} = 10 µF,
I_{OUT} slew rate = 1 A/µs

图 8-9. I_{OUT} Transient From 1 mA to 600 mA

9 Power Supply Recommendations

This device is designed to operate from an input supply voltage range of 1.95 V to 6.0 V. The input supply must be well regulated and free of spurious noise. To ensure that the output voltage is well regulated and dynamic performance is optimum, the input supply must be at least $V_{OUT(nom)}$ + 0.75 V. TI requires using a 1-µF or greater input capacitor to reduce the impedance of the input supply, especially during transients.

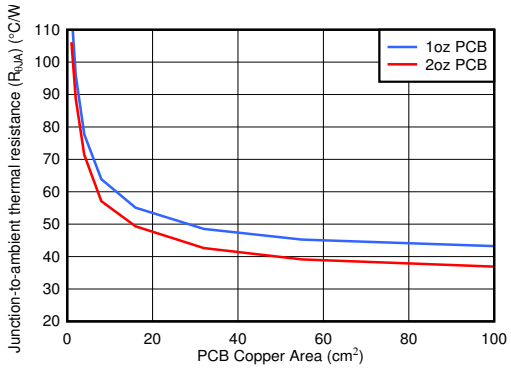
10 Layout

10.1 Layout Guidelines

- Place input and output capacitors as close to the device as possible.
- Use copper planes for device connections in order to optimize thermal performance.
- Place thermal vias around the device to distribute the heat.
- Only place tented thermal vias directly beneath the thermal pad of the DRB package. An untented via can wick solder or solder paste away from the thermal pad joint during the soldering process, leading to a compromised solder joint on the thermal pad.

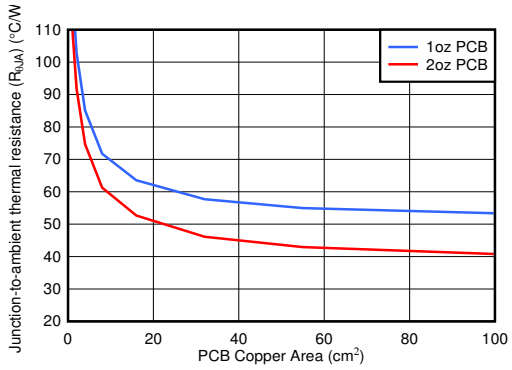
10.1.1 Additional Layout Considerations

The high impedance of the FB pin makes the regulator sensitive to parasitic capacitances that may couple undesirable signals from nearby components (especially from logic and digital devices, such as microcontrollers and microprocessors); these capacitively coupled signals may produce undesirable output voltage transients. In these cases, TI recommends using a fixed-voltage version of the device, or isolating the FB node by placing a copper ground plane on the layer directly underneath the LDO circuitry and FB pin to minimize any undesirable signal coupling.



4-layer PCB

图 10-1. Junction-to-Ambient Thermal Resistance ($R_{\theta JA}$) vs PCB Copper Area (DRB Package)



2-layer PCB

图 10-2. Junction-to-Ambient Thermal Resistance ($R_{\theta JA}$) vs PCB Copper Area (DRB Package)

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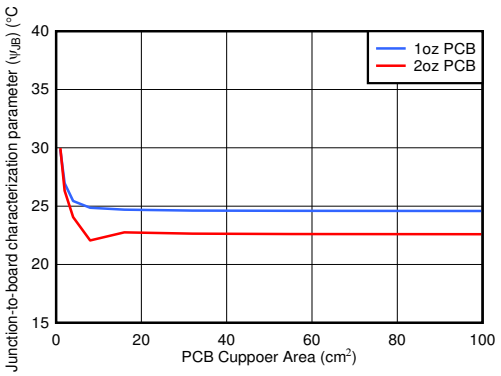
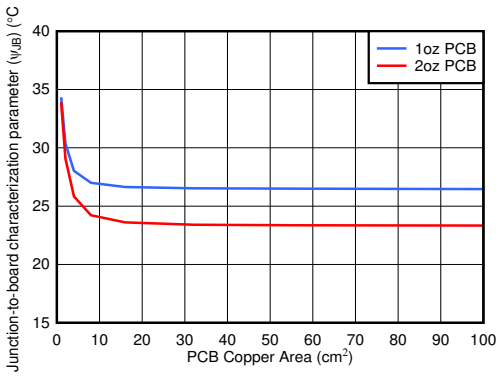


4-layer PCB

图 10-3. Junction-to-Board Characterization Parameter (ψ_{JB}) vs PCB Copper Area (DRB Package)



2-layer PCB

图 10-4. Junction-to-Board Characterization Parameter (ψ_{JB}) vs PCB Copper Area (DRB Package)

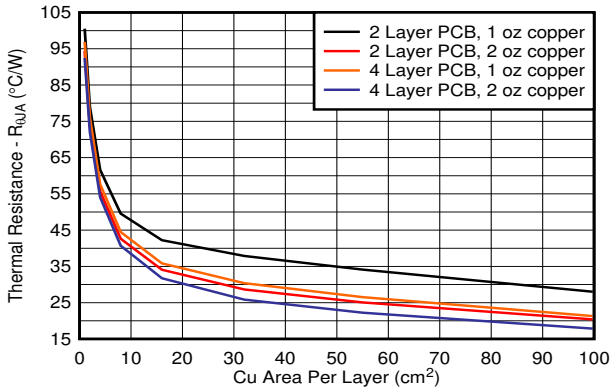


图 10-5. Junction-to-Ambient Thermal Resistance ($R_{\theta JA}$) vs PCB Copper Area (KVU Package)

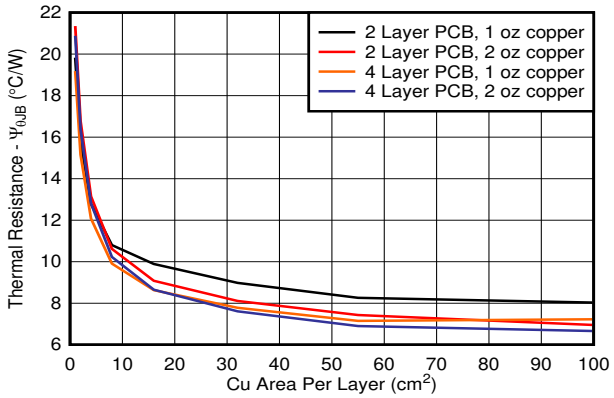


图 10-6. Junction-to-Board Characterization Parameter (ψ_{JB}) vs PCB Copper Area (KVU Package)

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10.2 Layout Examples

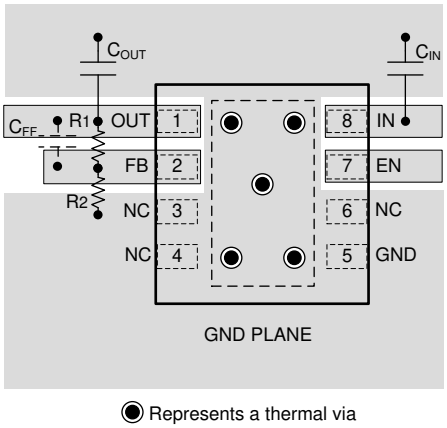

图 10-7. Layout Example for the DRB Package Adjustable Version

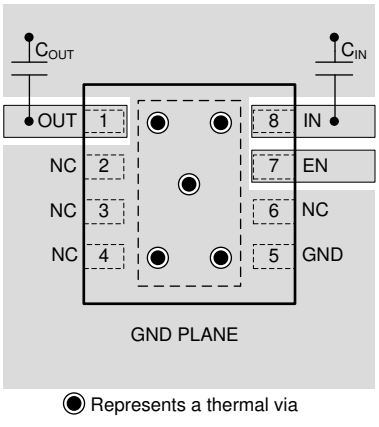

图 10-8. Layout Example for the DRB Package Fixed Version

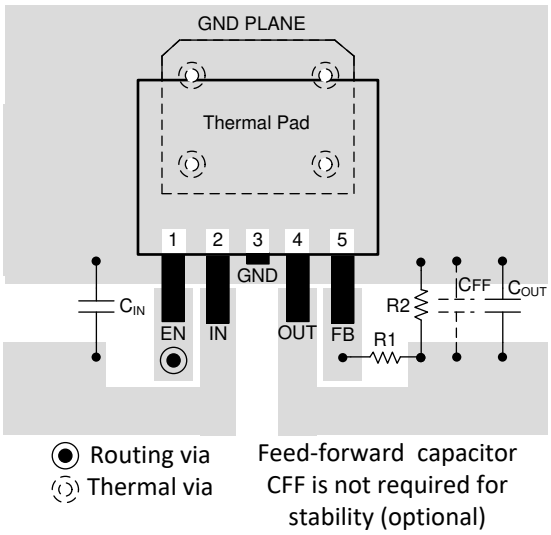

图 10-9. Layout Example for the KVU Package Adjustable Version

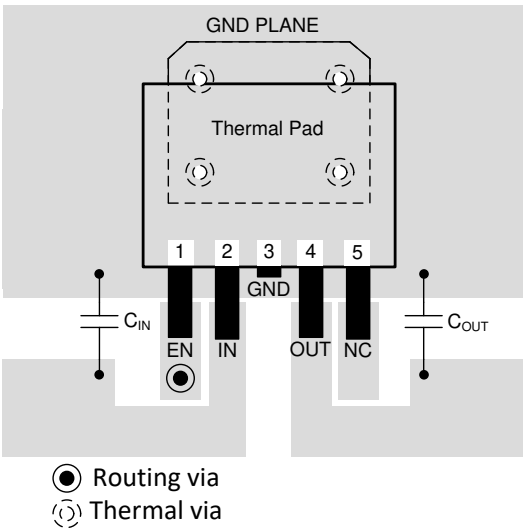

图 10-10. Layout Example for the KVU Package Fixed Version

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11 Device and Documentation Support

11.1 Device Support

11.1.1 Device Nomenclature

表 11-1. Device Nomenclature

PRODUCT(1) (2)	V_{OUT}
TPS785**xx(x)Q(W)yyyRQ1**	**xx(x)** is the nominal output voltage. For output voltages with a resolution of 100 mV, two digits are used in the ordering number; otherwise, three digits are used (for example, 28 = 2.8 V or 01 = adjustable). **W** denotes a wettable flank package. **yyy** is the package designator.

(1) For the most current package and ordering information see the *Package Option Addendum* at the end of this document, or visit the device product folder on www.ti.com.
(2) Output voltages from 0.65 V to 5.5 V in 50-mV increments are available. Contact the factory for details and availability.

11.2 Documentation Support

11.2.1 Related Documentation

For related documentation see the following:

- Texas Instruments, *Universal Low-Dropout (LDO) Linear Voltage Regulator MultiPkgLDOEVM-823 Evaluation Module* user's guide
- Texas Instruments, *Pros and Cons of Using a Feedforward Capacitor with a Low-Dropout Regulator* application report
- Texas Instruments, *An empirical analysis of the impact of board layout on LDO thermal performance* application report

11.3 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.4 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

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11.6 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.7 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS78501QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8501QKVU	Samples
TPS78501QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8501QW	Samples
TPS785075QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	85075Q	Samples
TPS78510QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8510QKVU	Samples
TPS78510QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8510QW	Samples
TPS78511QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8511QKVU	Samples
TPS78511QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8511QW	Samples
TPS78512QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8512QKVU	Samples
TPS78512QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8512QW	Samples
TPS78518QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8518QKVU	Samples
TPS78518QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8518QW	Samples
TPS78533QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8533QKVU	Samples
TPS78533QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8533QW	Samples
TPS78550QKVURQ1	ACTIVE	TO-252	KVU	5	2500	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 150	8550QKVU	Samples
TPS78550QWDRBRQ1	ACTIVE	SON	DRB	8	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 150	8550QW	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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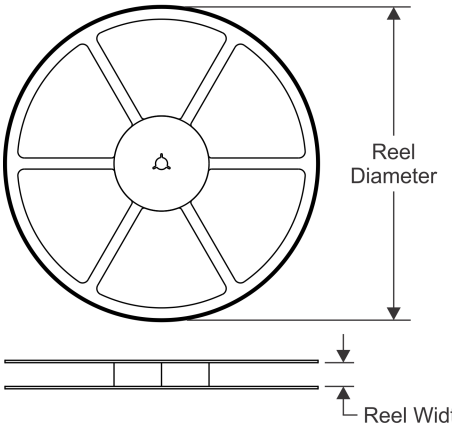
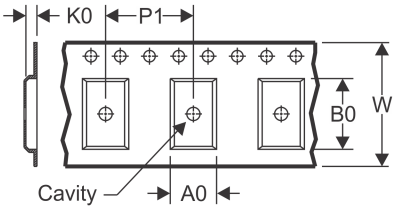
TAPE AND REEL INFORMATION

REEL DIMENSIONS

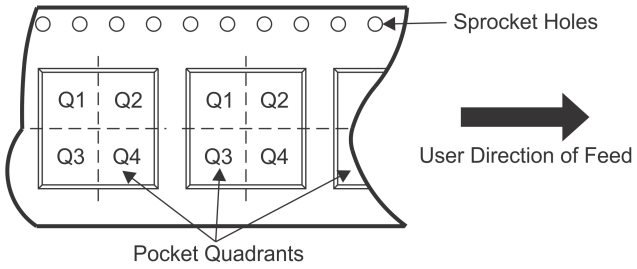


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

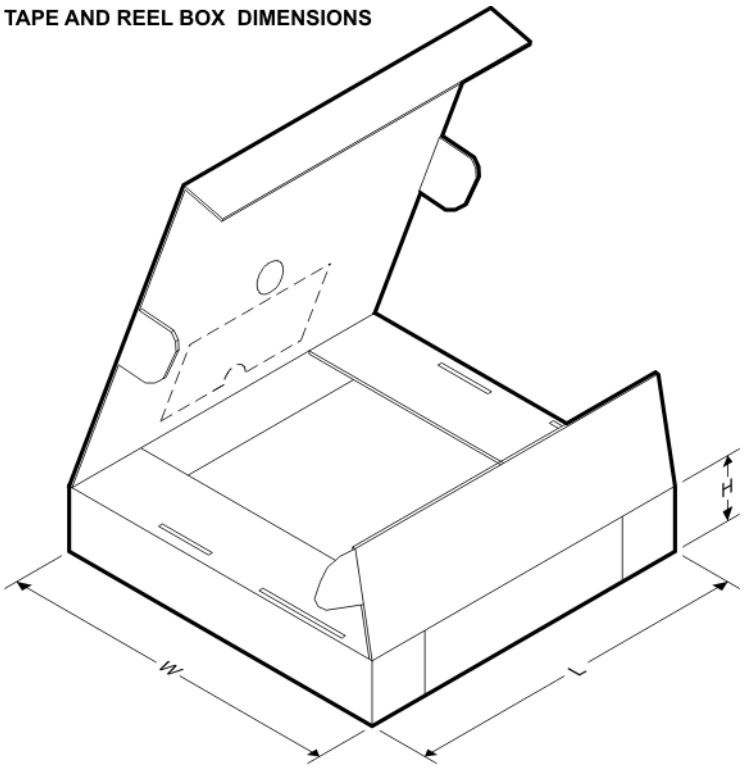
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS78501QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS78510QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS78511QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS78512QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS78518QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS78533QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
TPS78550QKVURQ1	TO-252	KVU	5	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS78501QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0
TPS78510QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0
TPS78511QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0
TPS78512QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0
TPS78518QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0
TPS78533QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0
TPS78550QKVURQ1	TO-252	KVU	5	2500	340.0	340.0	38.0

GENERIC PACKAGE VIEW

DRB 8 VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

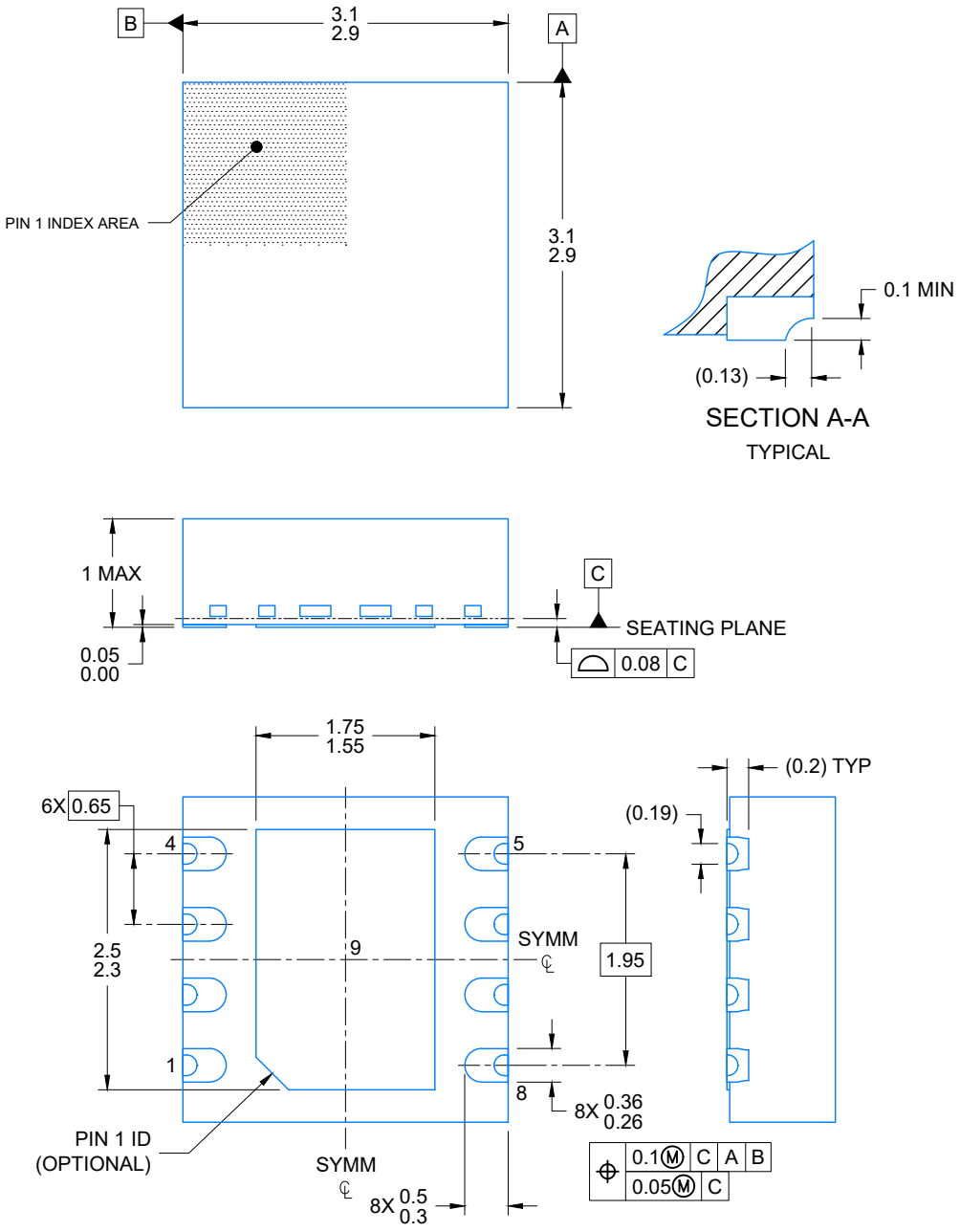
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

PACKAGE OUTLINE

DRB0008J

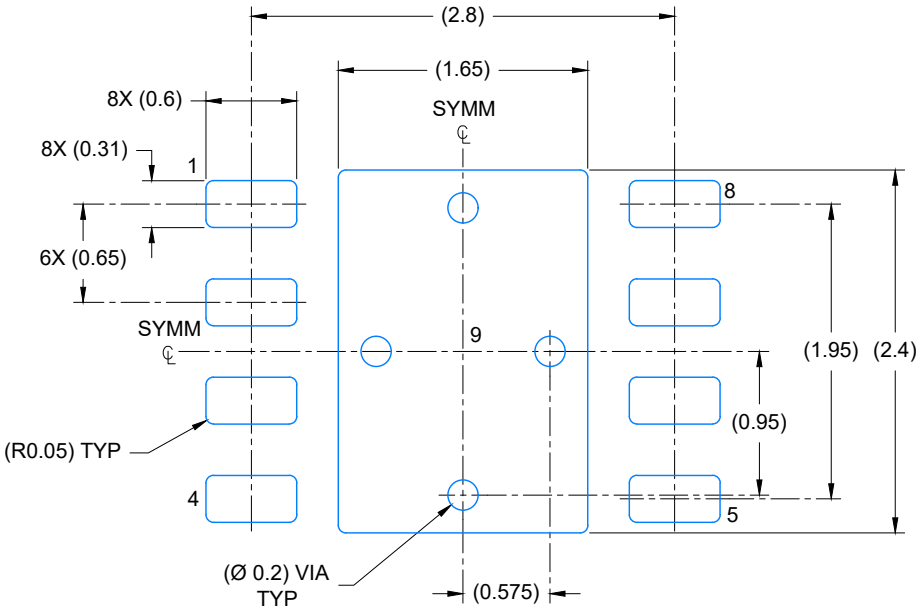
VSON - 1 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD

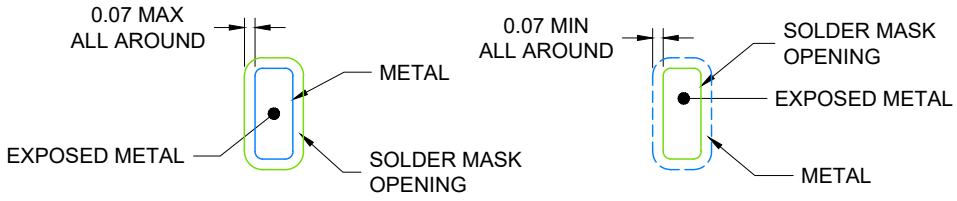


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



NON- SOLDER MASK
DEFINED
(PREFERRED)

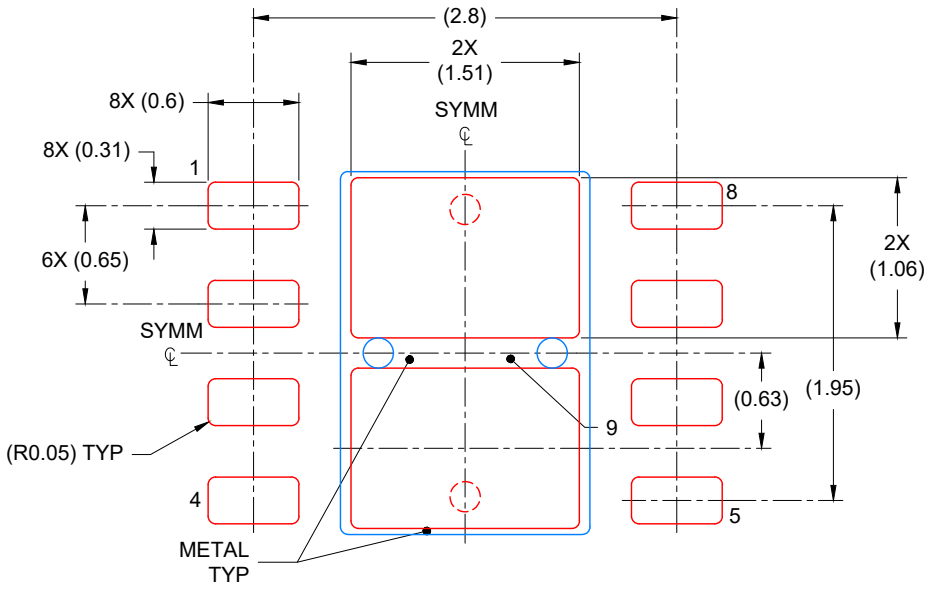
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4225036/A 06/2019

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

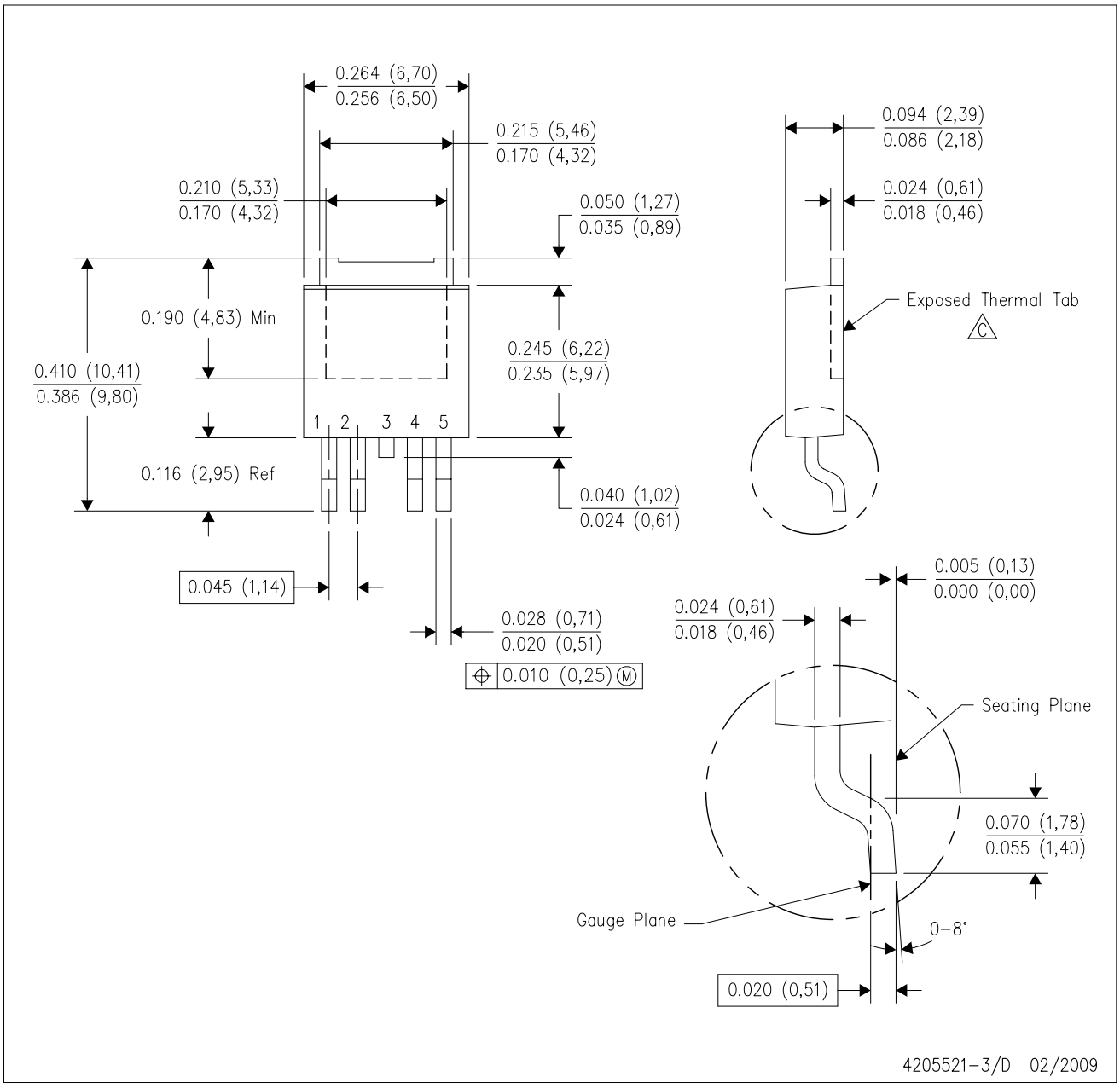
EXPOSED PAD
81% PRINTED COVERAGE BY AREA
SCALE: 20X

4225036/A 06/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

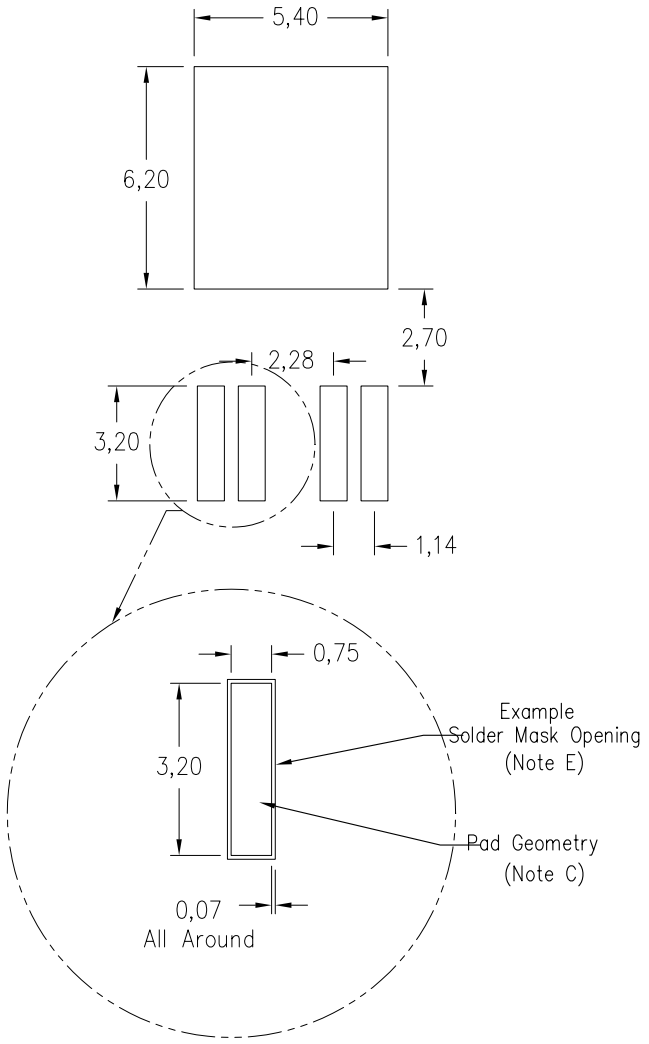
KVU (R–PSFM–G5) PLASTIC FLANGE–MOUNT PACKAGE



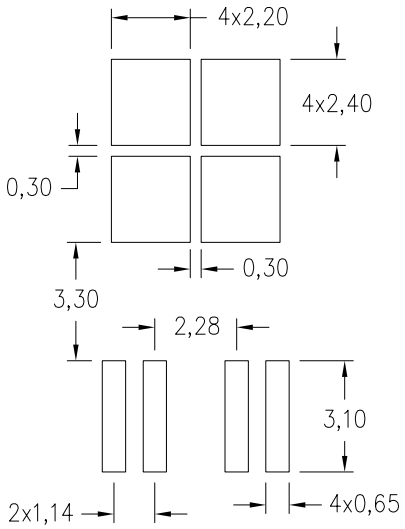
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. The center lead is in electrical contact with the exposed thermal tab.
D. Body Dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.006 (0,15) per side.
E. Falls within JEDEC TO–252 variation AD.

KVU (R–PSFM–G5) PLASTIC FLANGE MOUNT PACKAGE

Example Board Layout



Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).



63% solder coverage on center pad

4211592–3/B 03/12

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–SM–782 is an alternate information source for PCB land pattern designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in thermal pad.

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